

To all our customers

Regarding the change of names mentioned in the document, such as Mitsubishi Electric and Mitsubishi XX, to Renesas Technology Corp.

The semiconductor operations of Hitachi and Mitsubishi Electric were transferred to Renesas Technology Corporation on April 1st 2003. These operations include microcomputer, logic, analog and discrete devices, and memory chips other than DRAMs (flash memory, SRAMs etc.) Accordingly, although Mitsubishi Electric, Mitsubishi Electric Corporation, Mitsubishi Semiconductors, and other Mitsubishi brand names are mentioned in the document, these names have in fact all been changed to Renesas Technology Corp. Thank you for your understanding. Except for our corporate trademark, logo and corporate statement, no changes whatsoever have been made to the contents of the document, and these changes do not constitute any alteration to the contents of the document itself.

Note : Mitsubishi Electric will continue the business operations of high frequency & optical devices and power devices.

Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

DESCRIPTION

The 7531 Group is the 8-bit microcomputer based on the 740 family core technology.

The 7531 Group has a serial I/O, 8-bit timers, and an A-D converter, and is useful for control of home electric appliances and office automation equipment.

FEATURES

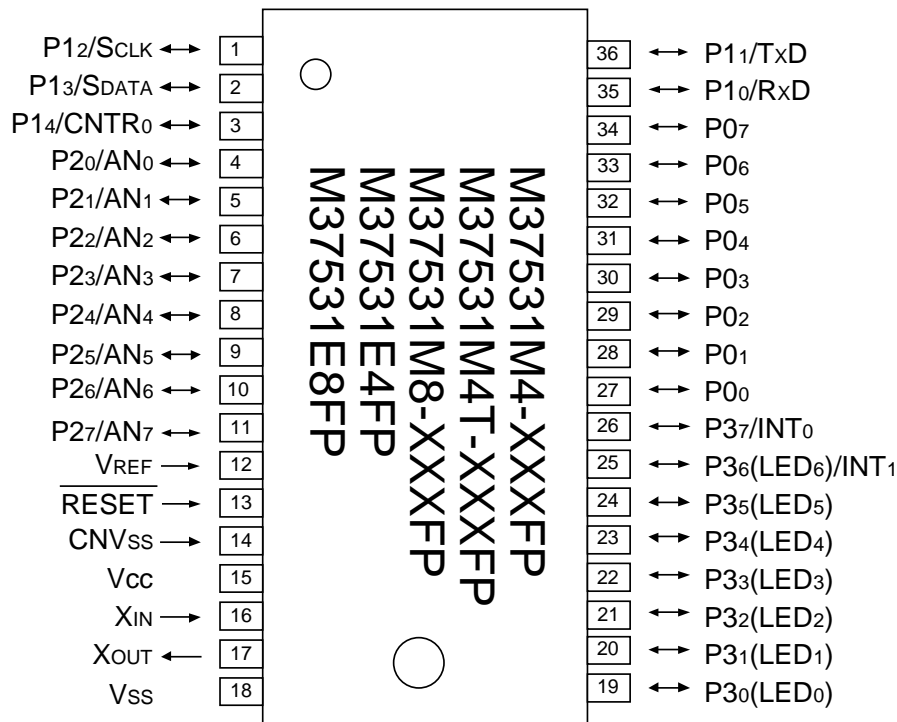
- Basic machine-language instructions 69
- The minimum instruction execution time 0.50 μ s
(at 8 MHz oscillation frequency for the shortest instruction, in high-speed mode)
- Memory size ROM 8K to 16K bytes
RAM 256 to 384 bytes
- Programmable I/O ports 29
(25 in 32-pin version)
- Interrupts 12 sources, 8 vectors
(11 sources, 8 vectors for 32-pin version)
- Timers 8-bit \times 3
- Serial I/O1 8-bit \times 1
(UART)
- Serial I/O2 8-bit \times 1
(Clock-synchronized)
- A-D converter 10-bit \times 8 channels
(6 channels for 32-pin version)
- Clock generating circuit Built-in type
(connect to external ceramic resonator or quartz-crystal oscillator permitting RC oscillation)

- Watchdog timer 16-bit \times 1
- Power source voltage
At 8 MHz XIN oscillation frequency at ceramic oscillation 4.0 to 5.5 V
At 4 MHz XIN oscillation frequency at ceramic oscillation 2.4 to 5.5 V
At 2 MHz XIN oscillation frequency at ceramic oscillation 2.2 to 5.5 V
At 4 MHz XIN oscillation frequency at RC oscillation 4.0 to 5.5 V
At 2 MHz XIN oscillation frequency at RC oscillation 2.4 to 5.5 V
At 1 MHz XIN oscillation frequency at RC oscillation 2.2 to 5.5 V
- Power dissipation 25 mW (standard)
- Operating temperature range -20 to 85 $^{\circ}$ C
(-40 to 85 $^{\circ}$ C or -40 to 125 $^{\circ}$ C for extended operating temperature version)

APPLICATION

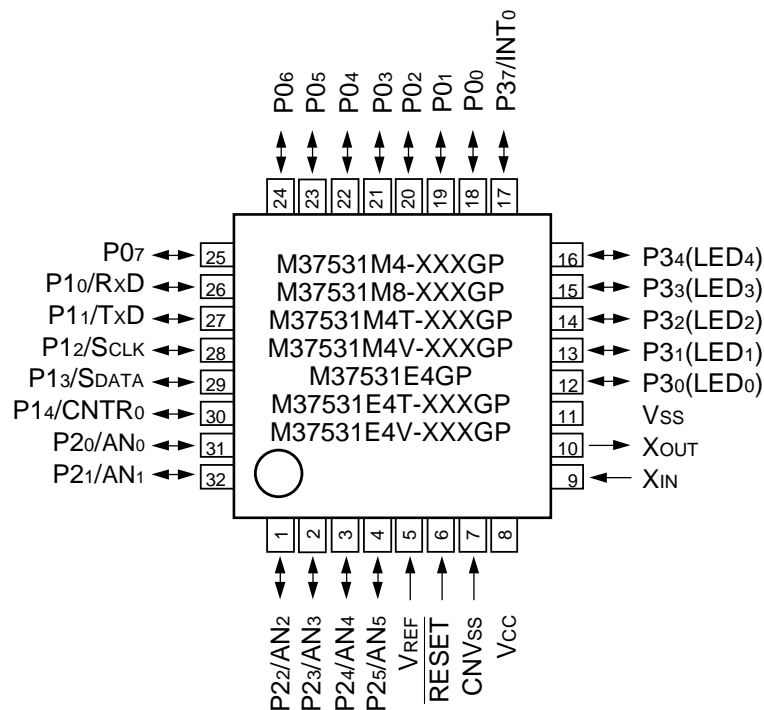
Office automation equipment, factory automation equipment, home electric appliances, consumer electronics, car, etc.

PIN CONFIGURATION (TOP VIEW)



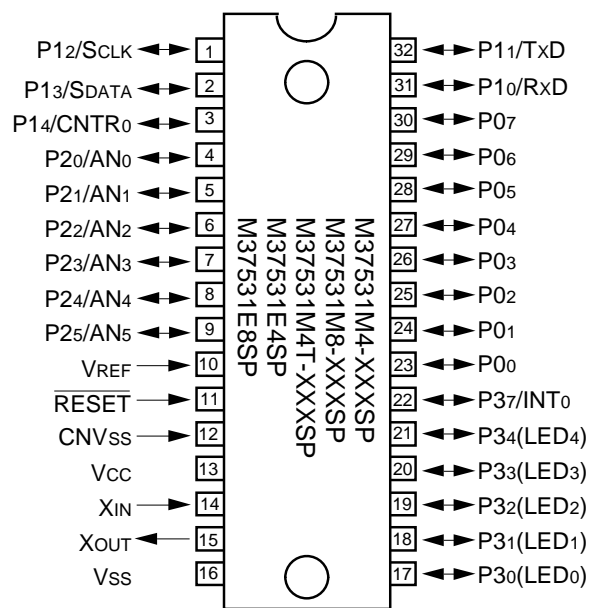
Package type: 36P2R-A

Fig. 1 Pin configuration (36P2R package type)



Package type: 32P6B-A

Fig. 2 Pin configuration (32P6B package type)



Package type: 32P4B

Fig. 3 Pin configuration (32P4B package type)

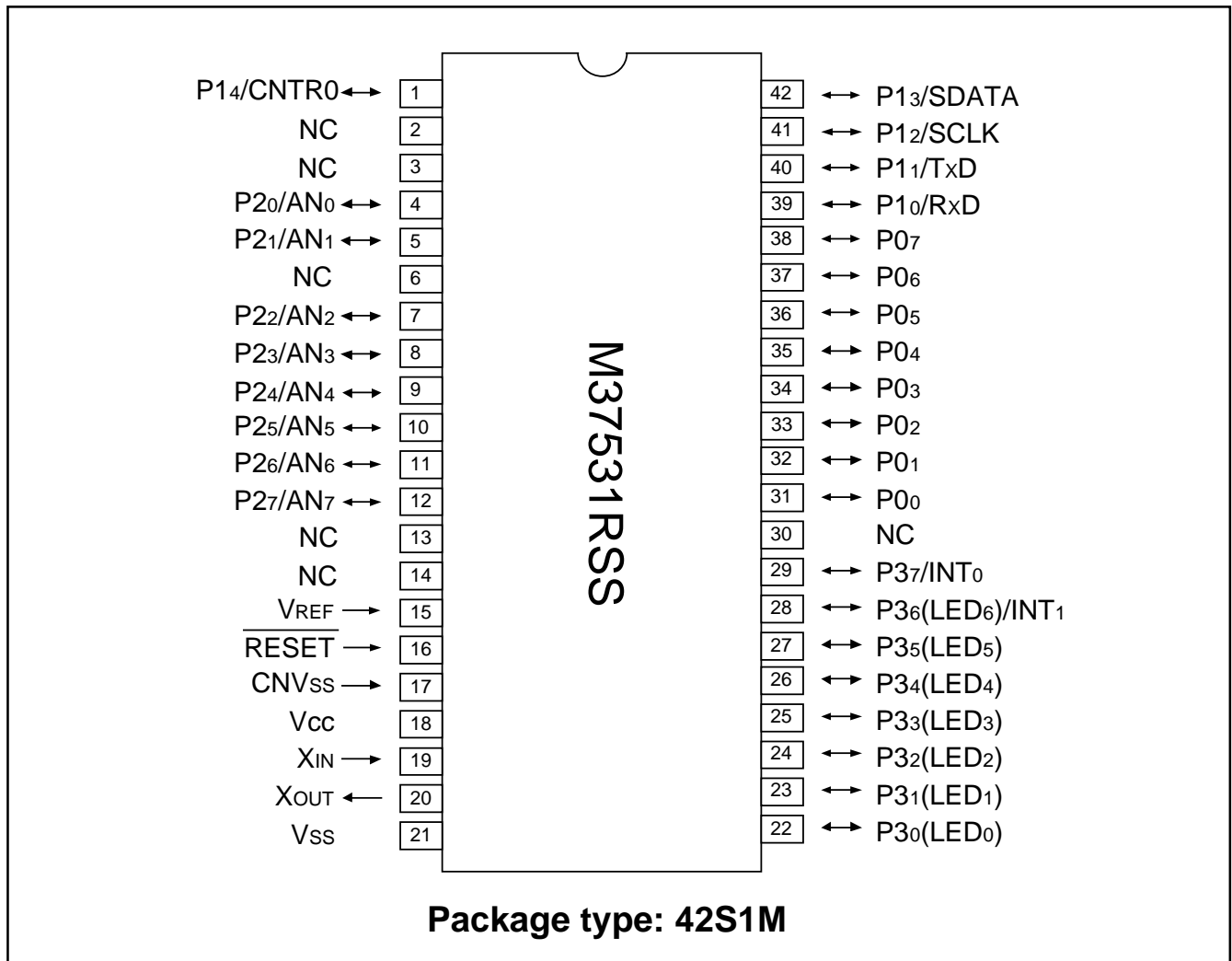


Fig. 4 Pin configuration (42S1M package type)

FUNCTIONAL BLOCK

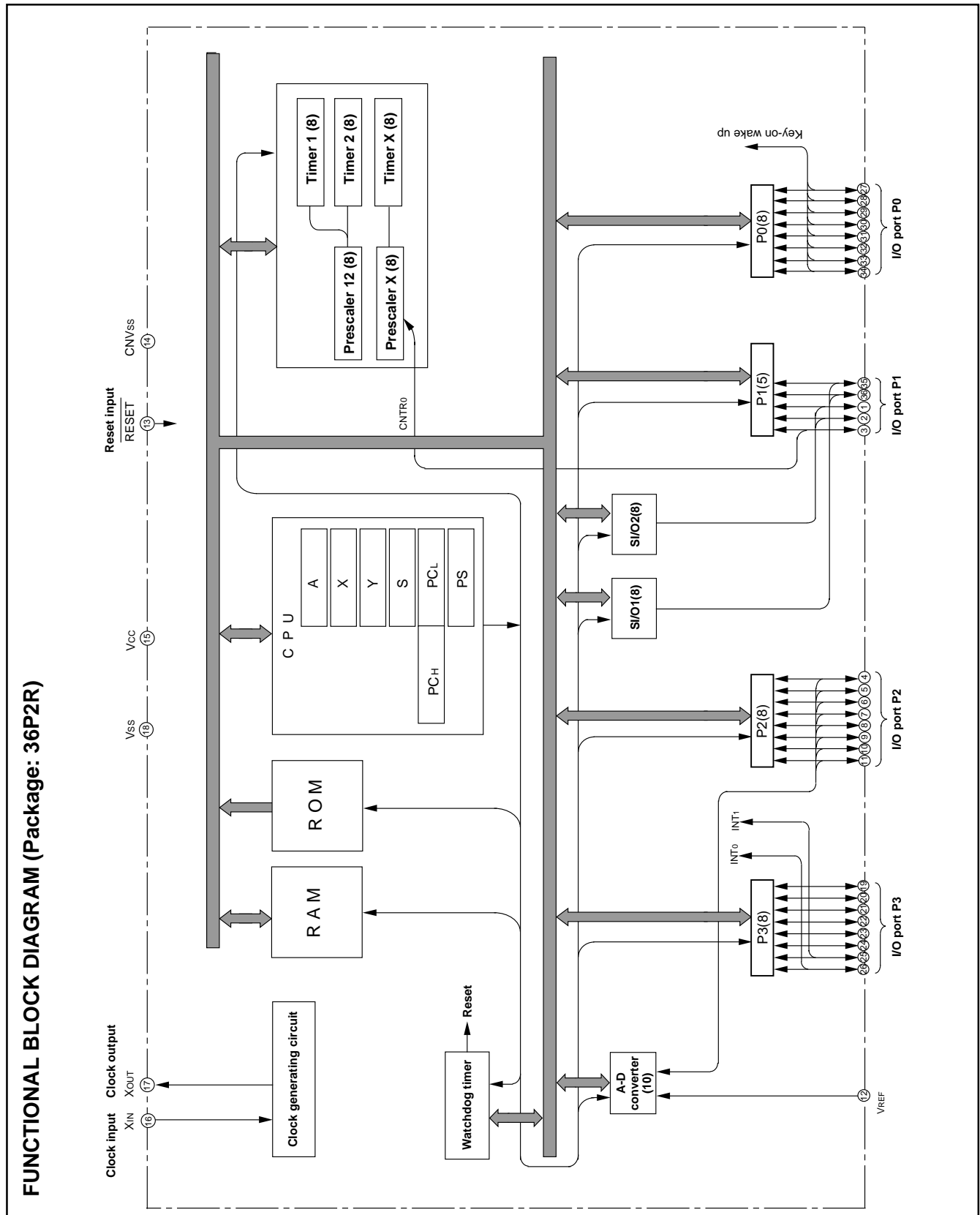


Fig. 5 Functional block diagram (36P2R package)

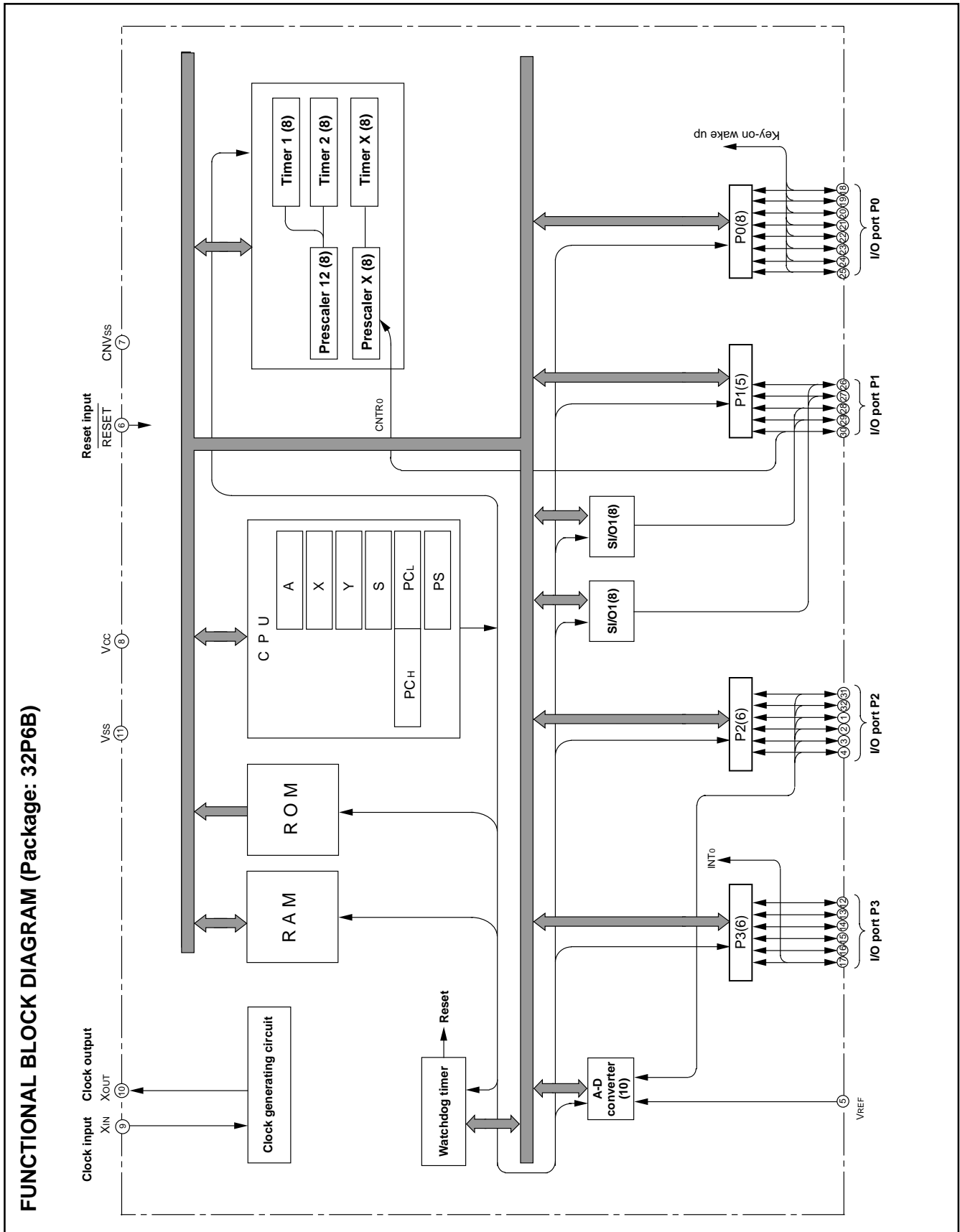


Fig. 6 Functional block diagram (32P6B package)

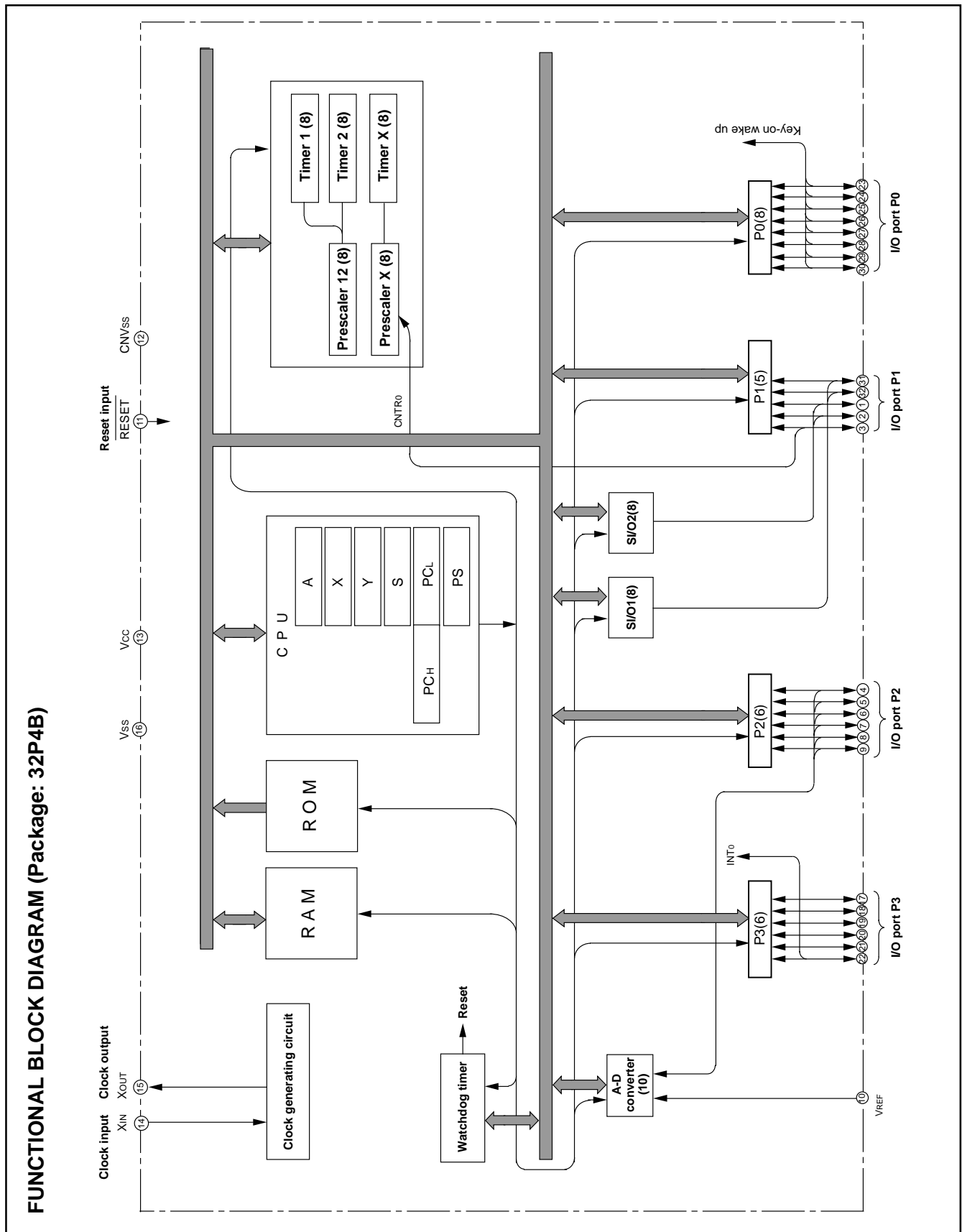


Fig. 7 Functional block diagram (32P4B package)

PIN DESCRIPTION

Table 1 Pin description

Pin	Name	Function	Function expect a port function
Vcc, Vss	Power source (Note 1)	•Apply voltage of 2.2–5.5 V to Vcc, and 0 V to Vss.	
VREF	Analog reference voltage	•Reference voltage input pin for A-D converter	
CNVss	CNVss	•Chip operating mode control pin, which is always connected to Vss.	
RESET	Reset input	•Reset input pin for active “L”	
XIN	Clock input	•Input and output pins for main clock generating circuit •Connect a ceramic resonator or quartz crystal oscillator between the XIN and XOUT pins.	
XOUT	Clock output	•For using RC oscillator, short between the XIN and XOUT pins, and connect the capacitor and resistor. •If an external clock is used, connect the clock source to the XIN pin and leave the XOUT pin open.	
P0 ₀ –P0 ₇	I/O port P0	•8-bit I/O port. •I/O direction register allows each pin to be individually programmed as either input or output. •CMOS compatible input level •CMOS 3-state output structure •Whether a built-in pull-up resistor is to be used or not can be determined by program.	•Key-input (key-on wake up interrupt input) pins
P1 ₀ /RxD P1 ₁ /TxD P1 ₂ /SCLK P1 ₃ /SDATA P1 ₄ /CNTR ₀	I/O port P1	•5-bit I/O port •I/O direction register allows each pin to be individually programmed as either input or output. •CMOS compatible input level •CMOS 3-state output structure •CMOS/TTL level can be switched for P1 ₀ , P1 ₂ and P1 ₃	•Serial I/O1 function pin •Serial I/O2 function pin •Timer X function pin
P2 ₀ /AN ₀ – P2 ₇ /AN ₇	I/O port P2 (Note 2)	•8-bit I/O port having almost the same function as P0 •CMOS compatible input level •CMOS 3-state output structure	•Input pins for A-D converter
P3 ₀ –P3 ₅ P3 ₆ /INT ₁ P3 ₇ /INT ₀	I/O port P3 (Note 3)	•8-bit I/O port •I/O direction register allows each pin to be individually programmed as either input or output. •CMOS compatible input level (CMOS/TTL level can be switched for P3 ₆ and P3 ₇). •CMOS 3-state output structure •P3 ₀ to P3 ₆ can output a large current for driving LED. •Whether a built-in pull-up resistor is to be used or not can be determined by program.	•Interrupt input pins

Notes 1: Vcc = 2.4 to 5.5 V for the extended operating temperature version (–40 to 85 °C) and the extended operating temperature 125 °C version (–40 to 125 °C).

2: 6-bit I/O port (P2₀–P2₅) for the 32-pin version.

3: 6-bit I/O port (P3₀–P3₄, P3₇/INT₀) for the 32-pin version.

GROUP EXPANSION

Mitsubishi plans to expand the 7531 group as follow:

Memory type

Support for Mask ROM version, One Time PROM version, and Emulator MCU .

Memory size

ROM/PROM size 8 K to 16 K bytes

RAM size 256 to 384 bytes

Package

32P4B 32 pin plastic molded SDIP

32P6B-A 0.8 mm-pitch plastic molded LQFP

36P2R-A 0.8 mm-pitch plastic molded SSOP

42S1M 42 pin shrink ceramic PIGGY BACK

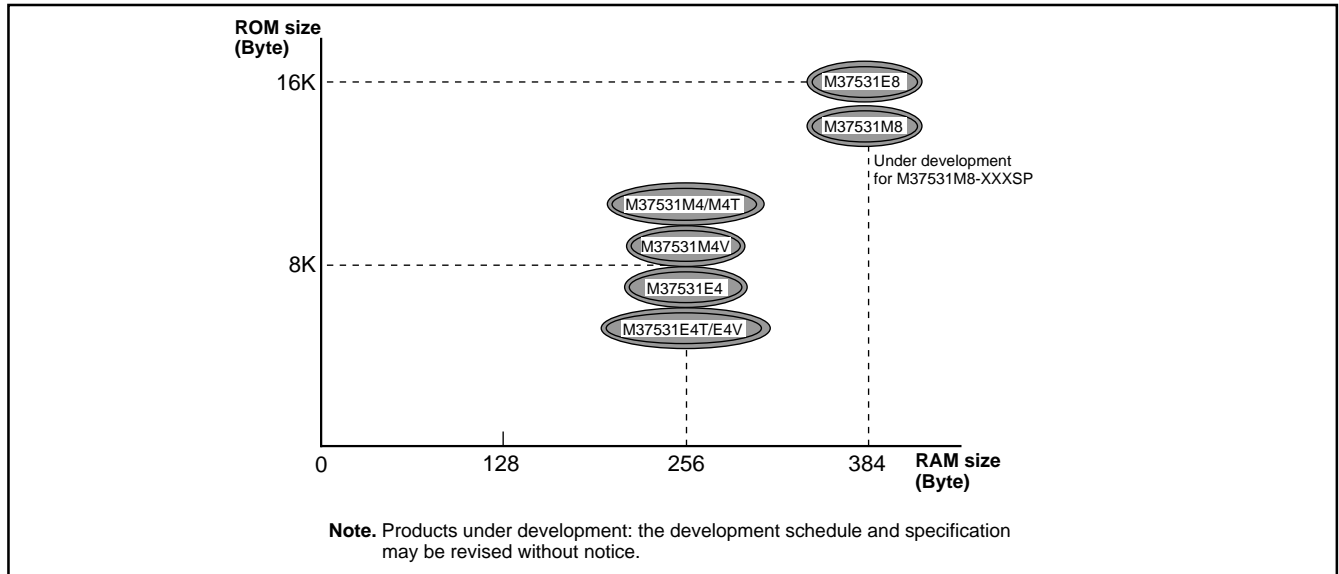


Fig. 8 Memory expansion plan

Currently supported products are listed below.

Table 2 List of supported products

Product	(P) ROM size (bytes) ROM size for User ()	RAM size (bytes)	Package	Remarks
M37531M4-XXXSP	8192 (8062)	256	32P4B	Mask ROM version
M37531M4T-XXXSP				Mask ROM version (extended operating temperature version)
M37531E4SP				One Time PROM version (blank)
M37531M4-XXXFP			36P2R-A	Mask ROM version
M37531M4T-XXXFP				Mask ROM version (extended operating temperature version)
M37531E4FP				One Time PROM version (blank)
M37531M4-XXXGP			32P6B-A	Mask ROM version
M37531M4T-XXXGP				Mask ROM version (extended operating temperature version)
M37531M4V-XXXGP				Mask ROM version (extended operating temperature 125 °C version)
M37531E4GP				One Time PROM version (blank)
M37531E4T-XXXGP				One Time PROM version (shipped after programming, extended operating temperature version)
M37531E4V-XXXGP				One Time PROM version (shipped after programming, extended operating temperature 125 °C version)
M37531M8-XXXSP	16384 (16254)	384	32P4B	Mask ROM version
M37531E8SP				One Time PROM version (blank)
M37531M8-XXXFP			36P2R-A	Mask ROM version
M37531E8FP				One Time PROM version (blank)
M37531M8-XXXGP			32P6B-A	Mask ROM version
M37531RSS			42S1M	Emulator MCU

FUNCTIONAL DESCRIPTION

CPU

[CPU Mode Register] CPUM

The CPU mode register contains the stack page selection bit. This register is allocated at address 003B₁₆.

Switching method of CPU mode register

Switch the CPU mode register (CPUM) at the head of program after releasing Reset in the following method.

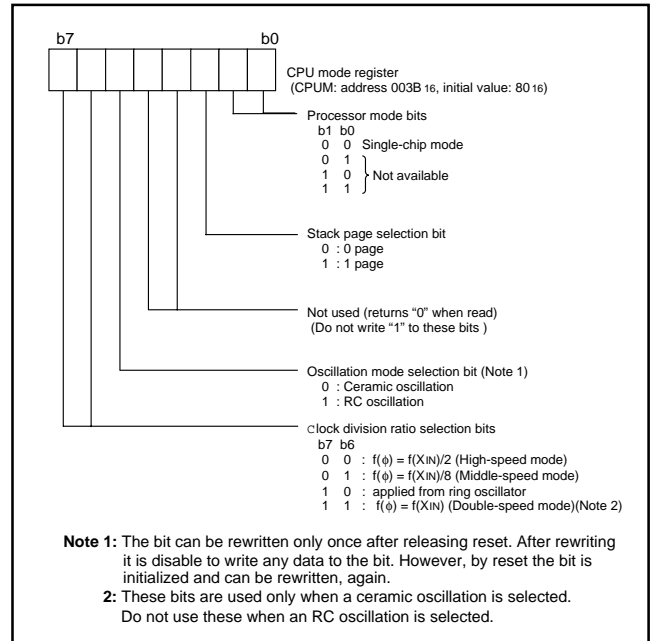


Fig. 9 Structure of CPU mode register

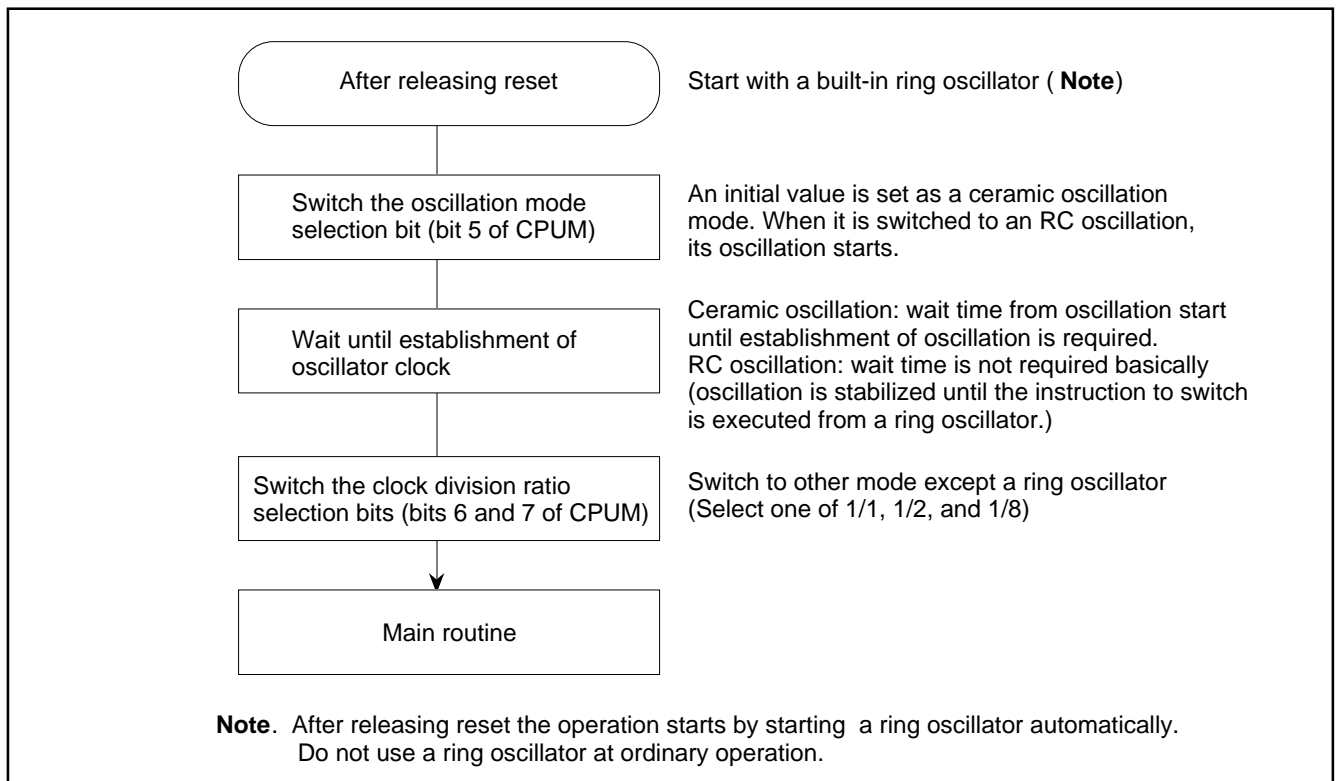


Fig. 10 Switching method of CPU mode register

Memory

Special function register (SFR) area

The SFR area in the zero page contains control registers such as I/O ports and timers.

RAM

RAM is used for data storage and for a stack area of subroutine calls and interrupts.

ROM

The first 128 bytes and the last 2 bytes of ROM are reserved for device testing and the rest is a user area for storing programs.

Interrupt vector area

The interrupt vector area contains reset and interrupt vectors.

Zero page

The 256 bytes from addresses 0000₁₆ to 00FF₁₆ are called the zero page area. The internal RAM and the special function registers (SFR) are allocated to this area.

The zero page addressing mode can be used to specify memory and register addresses in the zero page area. Access to this area with only 2 bytes is possible in the zero page addressing mode.

Special page

The 256 bytes from addresses FF00₁₆ to FFFF₁₆ are called the special page area. The special page addressing mode can be used to specify memory addresses in the special page area. Access to this area with only 2 bytes is possible in the special page addressing mode.

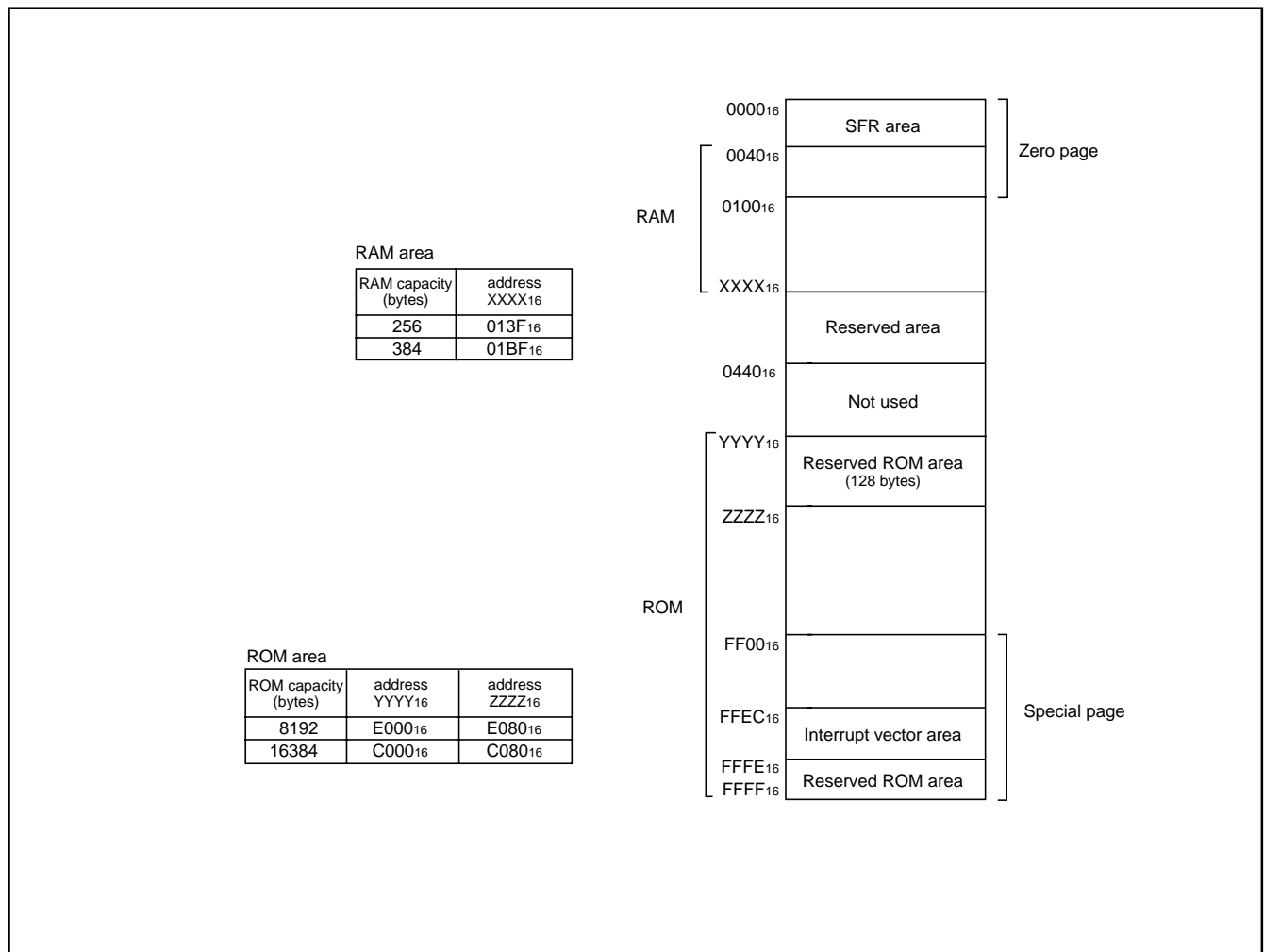


Fig. 11 Memory map diagram

0000 ₁₆	Port P0 (P0)	0020 ₁₆	
0001 ₁₆	Port P0 direction register (P0D)	0021 ₁₆	
0002 ₁₆	Port P1 (P1)	0022 ₁₆	
0003 ₁₆	Port P1 direction register (P1D)	0023 ₁₆	
0004 ₁₆	Port P2 (P2)	0024 ₁₆	
0005 ₁₆	Port P2 direction register (P2D)	0025 ₁₆	
0006 ₁₆	Port P3 (P3)	0026 ₁₆	
0007 ₁₆	Port P3 direction register (P3D)	0027 ₁₆	
0008 ₁₆		0028 ₁₆	Prescaler 12 (PRE12)
0009 ₁₆		0029 ₁₆	Timer 1 (T1)
000A ₁₆		002A ₁₆	Timer 2 (T2)
000B ₁₆		002B ₁₆	Timer X mode register (TM)
000C ₁₆		002C ₁₆	Prescaler X (PREX)
000D ₁₆		002D ₁₆	Timer X (TX)
000E ₁₆		002E ₁₆	Timer count source set register (TCSS)
000F ₁₆		002F ₁₆	
0010 ₁₆		0030 ₁₆	Serial I/O2 control register (SIO2CON)
0011 ₁₆		0031 ₁₆	Serial I/O2 register (SIO2)
0012 ₁₆		0032 ₁₆	
0013 ₁₆		0033 ₁₆	
0014 ₁₆		0034 ₁₆	A-D control register (ADCON)
0015 ₁₆		0035 ₁₆	A-D conversion register (low-order) (ADL)
0016 ₁₆	Pull-up control register (PULL)	0036 ₁₆	A-D conversion register (high-order) (ADH)
0017 ₁₆	Port P1P3 control register (P1P3C)	0037 ₁₆	
0018 ₁₆	Transmit/Receive buffer register (TB/RB)	0038 ₁₆	MISRG
0019 ₁₆	Serial I/O1 status register (SIO1STS)	0039 ₁₆	Watchdog timer control register (WDTCON)
001A ₁₆	Serial I/O1 control register (SIO1CON)	003A ₁₆	Interrupt edge selection register (INTEDGE)
001B ₁₆	UART control register (UARTCON)	003B ₁₆	CPU mode register (CPUM)
001C ₁₆	Baud rate generator (BRG)	003C ₁₆	Interrupt request register 1 (IREQ1)
001D ₁₆		003D ₁₆	
001E ₁₆		003E ₁₆	Interrupt control register 1 (ICON1)
001F ₁₆		003F ₁₆	

Note : Do not access to the SFR area including nothing.

Fig. 12 Memory map of special function register (SFR)

I/O Ports

[Direction registers] PiD

The I/O ports have direction registers which determine the input/output direction of each pin. Each bit in a direction register corresponds to one pin, and each pin can be set to be input or output.

When "1" is set to the bit corresponding to a pin, this pin becomes an output port. When "0" is set to the bit, the pin becomes an input port. When data is read from a pin set to output, not the value of the pin itself but the value of port latch is read. Pins set to input are floating, and permit reading pin values.

If a pin set to input is written to, only the port latch is written to and the pin remains floating.

[Pull-up control] PULL

By setting the pull-up control register (address 0016₁₆), ports P0 and P3 can exert pull-up control by program. However, pins set to output are disconnected from this control and cannot exert pull-up control.

[Port P1P3 control] P1P3C

By setting the port P1P3 control register (address 0017₁₆), a CMOS input level or a TTL input level can be selected for ports P10, P12, P13, P36, and P37 by program.

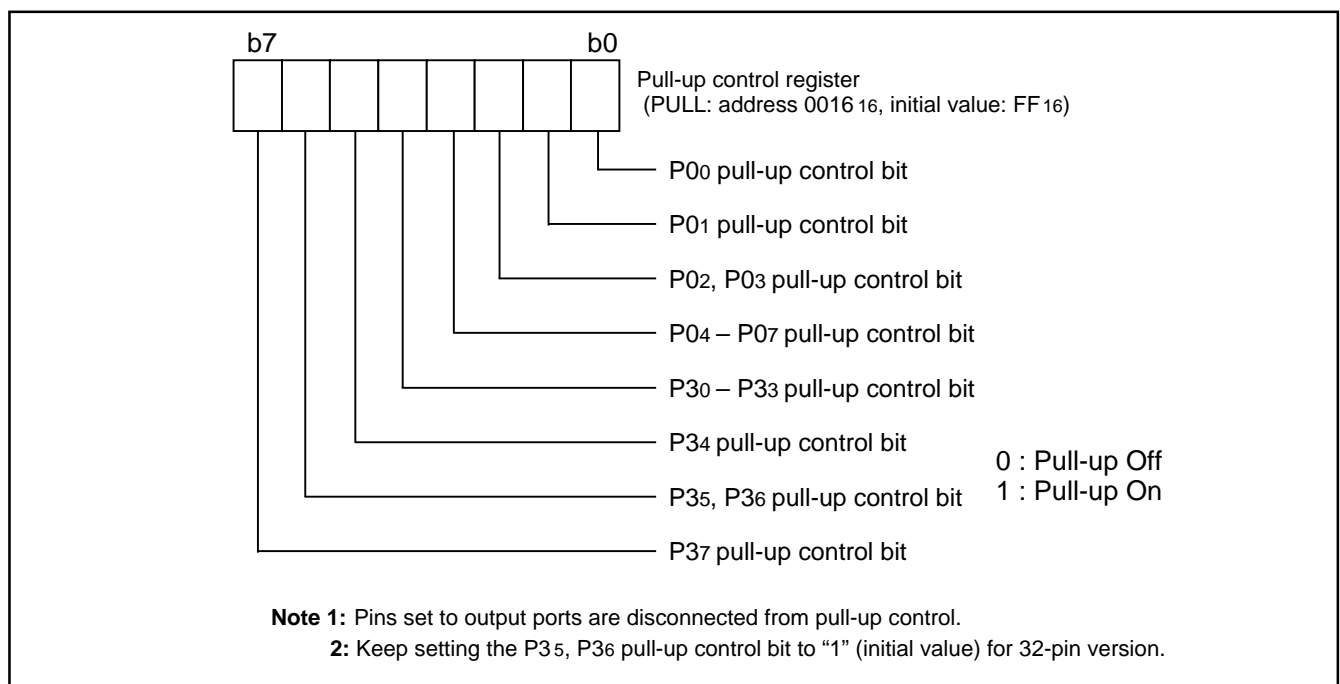


Fig. 13 Structure of pull-up control register

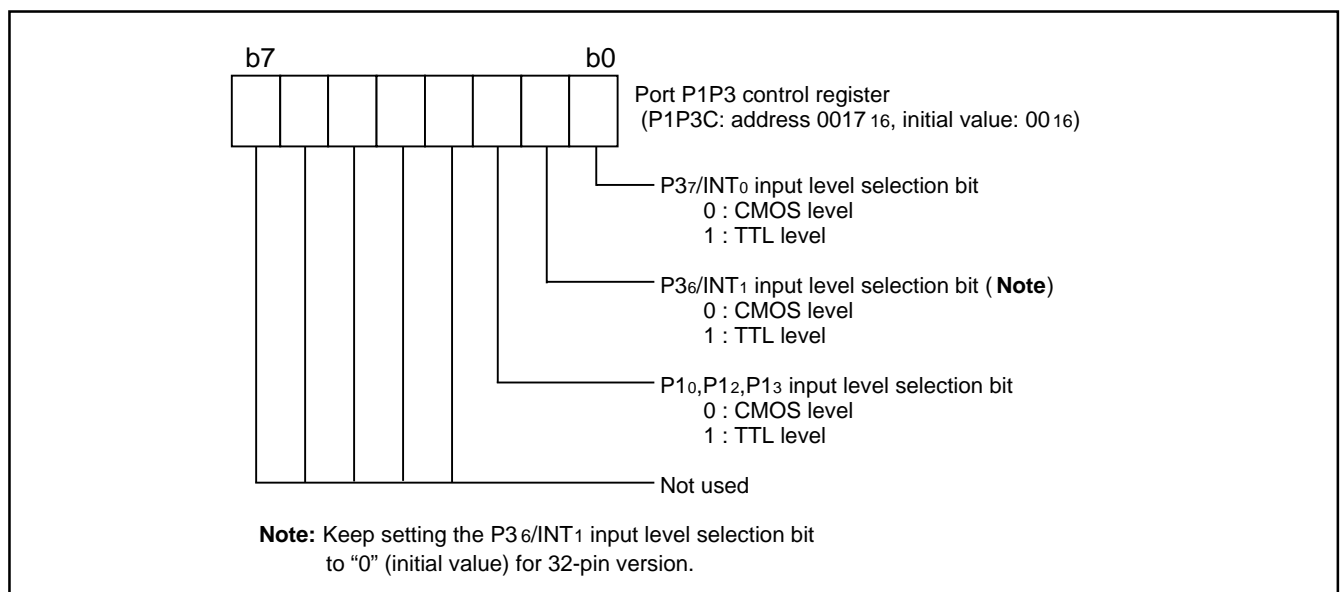


Fig. 14 Structure of port P1P3 control register

Table 5 I/O port function table

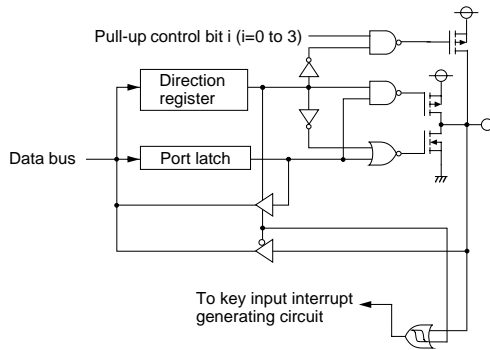
Pin	Name	Input/output	I/O format	Non-port function	Related SFRs	Diagram No.
P00–P07	I/O port P0	I/O individual bits	•CMOS compatible input level •CMOS 3-state output (Note 1)	Key input interrupt	Pull-up control register	(1)
P10/RxD	I/O port P1			Serial I/O1 function input/output	Serial I/O1 control register	(2)
P11/TxD						(3)
P12/SCLK				Serial I/O2 function input/output	Serial I/O2 control register	(4)
P13/SDATA						(5)
P14/CNTR0				Timer X function input/output	Timer X mode register	(6)
P20/AN0–P27/AN7	I/O port P2 (Note 2)			A-D conversion input	A-D control register	(7)
P30–P35	I/O port P3 (Note 3)					(8)
P36/INT1				External interrupt input	Interrupt edge selection register	(9)
P37/INT0						

Notes 1: Ports P10, P12, P13, P36, and P37 are CMOS/TTL level.

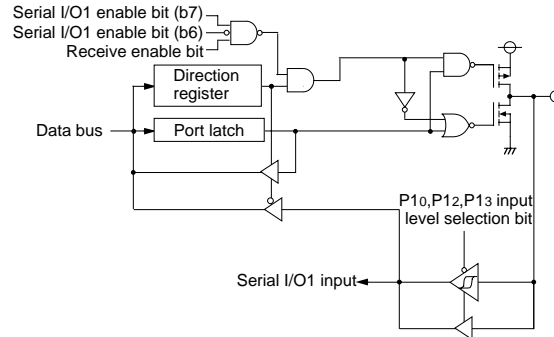
2: The P26/AN6 and P27/AN7 pins do not exist for the 32-pin version.

3: The P35 and P36/INT1 pins do not exist for the 32-pin version.

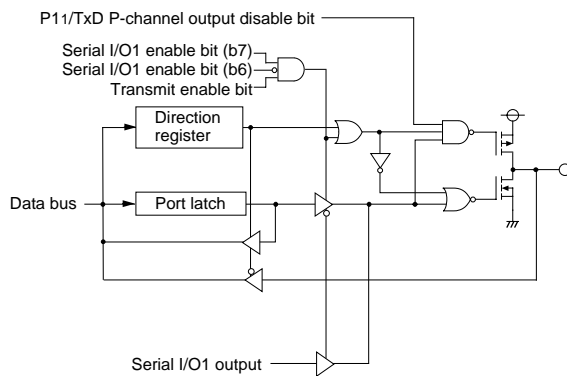
(1) Port P0



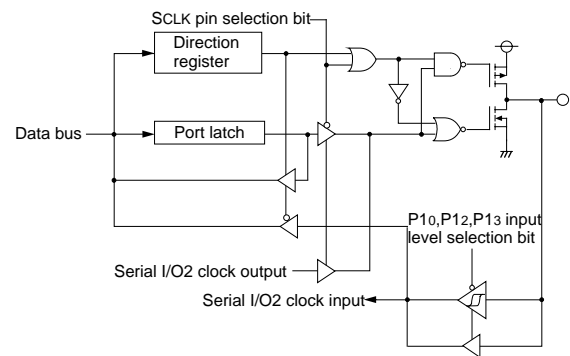
(2) Port P10



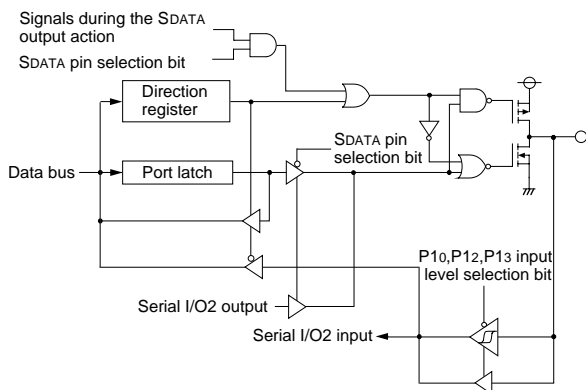
(3) Port P11



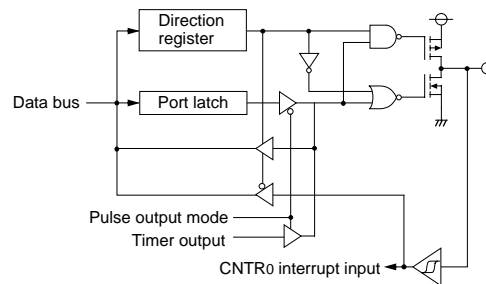
(4) Port P12



(5) Port P13

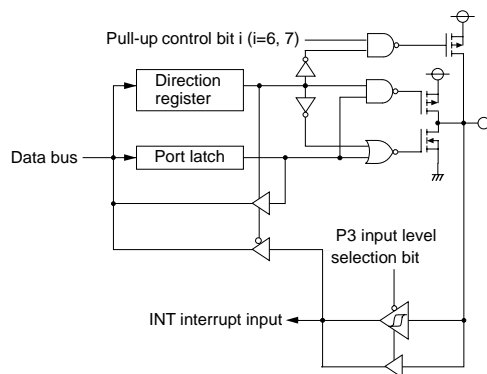
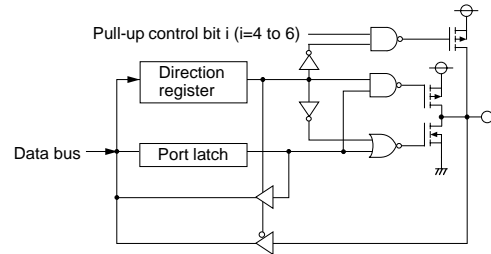
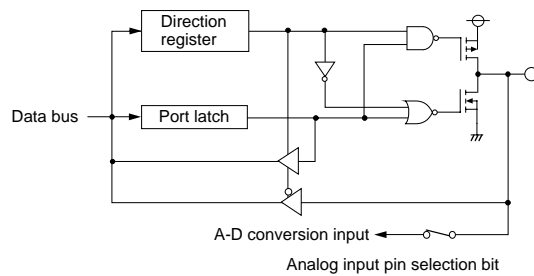


(6) Port P14



P10, P12, P13, P36, and P37 input level are switched to the CMOS/TTL level by the port P1P3 control register. When the TTL level is selected, there is no hysteresis characteristics.

Fig. 15 Block diagram of ports (1)



P10, P12, P13, P36, and P37 input level are switched to the CMOS/TTL level by the port P1P3 control register. When the TTL level is selected, there is no hysteresis characteristics.

Fig. 16 Block diagram of ports (2)

Interrupts

Interrupts occur by 12 different sources : 4 external sources, 7 internal sources and 1 software source.

Interrupt control

All interrupts except the BRK instruction interrupt have an interrupt request bit and an interrupt enable bit, and they are controlled by the interrupt disable flag. When the interrupt enable bit and the interrupt request bit are set to "1" and the interrupt disable flag is set to "0", an interrupt is accepted.

The interrupt request bit can be cleared by program but not be set.

The interrupt enable bit can be set and cleared by program.

It becomes usable by switching CNTR₀ and AD conversion interrupt sources with bit 7 of the interrupt edge selection register, timer 2 and serial I/O2 interrupt sources with bit 6, timer X and key-on wake-up interrupt sources with bit 5, and serial I/O1 transmit and INT₁ interrupt sources with bit 4.

The reset and BRK instruction interrupt can never be disabled with any flag or bit. All interrupts except these are disabled when the interrupt disable flag is set.

When several interrupts occur at the same time, the interrupts are received according to priority.

Interrupt operation

Upon acceptance of an interrupt the following operations are automatically performed:

1. The processing being executed is stopped.
2. The contents of the program counter and processor status register are automatically pushed onto the stack.
3. The interrupt disable flag is set and the corresponding interrupt request bit is cleared.
4. Concurrently with the push operation, the interrupt destination address is read from the vector table into the program counter.

Notes on use

When the active edge of an external interrupt (INT₀, INT₁, CNTR₀) is set, the interrupt request bit may be set.

Therefore, please take following sequence:

1. Disable the external interrupt which is selected.
2. Change the active edge in interrupt edge selection register. (in case of CNTR₀: Timer X mode register)
3. Clear the set interrupt request bit to "0".
4. Enable the external interrupt which is selected.

Table 6 Interrupt vector address and priority

Interrupt source	Priority	Vector addresses (Note 1)		Interrupt request generating conditions	Remarks
		High-order	Low-order		
Reset (Note 2)	1	FFFD ₁₆	FFFC ₁₆	At reset input	Non-maskable
Serial I/O1 receive	2	FFFB ₁₆	FFFA ₁₆	At completion of serial I/O1 data receive	Valid when serial I/O1 is selected
Serial I/O1 transmit	3	FFF9 ₁₆	FFF8 ₁₆	At completion of serial I/O1 transmit shift or when transmit buffer is empty	Valid when serial I/O1 is selected
INT ₁ (Note 3)				At detection of either rising or falling edge of INT ₁ input	External interrupt (active edge selectable)
INT ₀	4	FFF7 ₁₆	FFF6 ₁₆	At detection of either rising or falling edge of INT ₀ input	External interrupt (active edge selectable)
Timer X	5	FFF5 ₁₆	FFF4 ₁₆	At timer X underflow	External interrupt (valid at falling)
Key-on wake-up				At falling of conjunction of input logical level for port P0 (at input)	
Timer 1	6	FFF3 ₁₆	FFF2 ₁₆	At timer 1 underflow	STP release timer underflow
Timer 2				At timer 2 underflow	
Serial I/O2	7	FFF1 ₁₆	FFF0 ₁₆	At completion of transmit/receive shift	
CNTR ₀	8	FFEF ₁₆	FFEE ₁₆	At detection of either rising or falling edge of CNTR ₀ input	External interrupt (active edge selectable)
A-D conversion				At completion of A-D conversion	
BRK instruction	9	FFED ₁₆	FFEC ₁₆	At BRK instruction execution	Non-maskable software interrupt

Note 1: Vector addresses contain internal jump destination addresses.

2: Reset function in the same way as an interrupt with the highest priority.

3: It is an interrupt which can use only for 36 pin version.

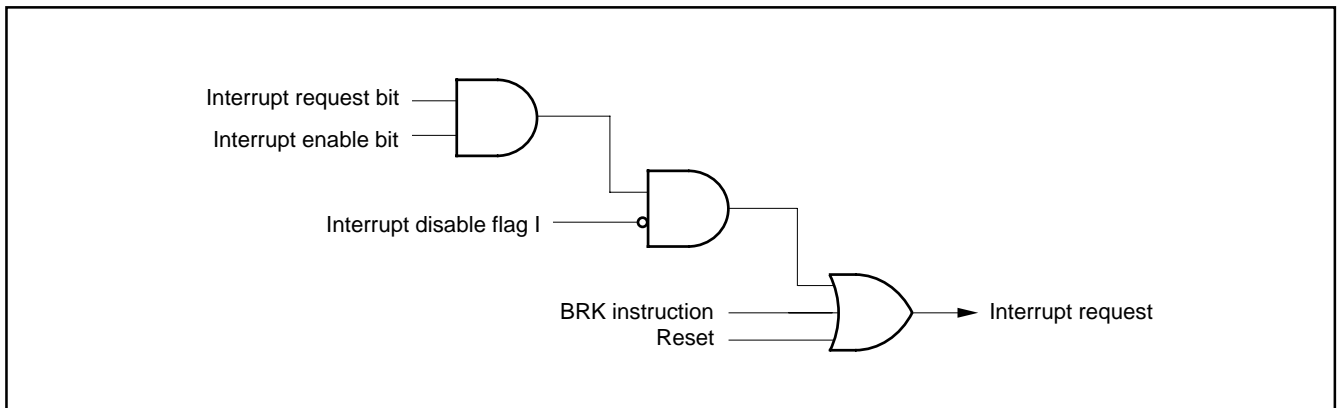


Fig. 17 Interrupt control

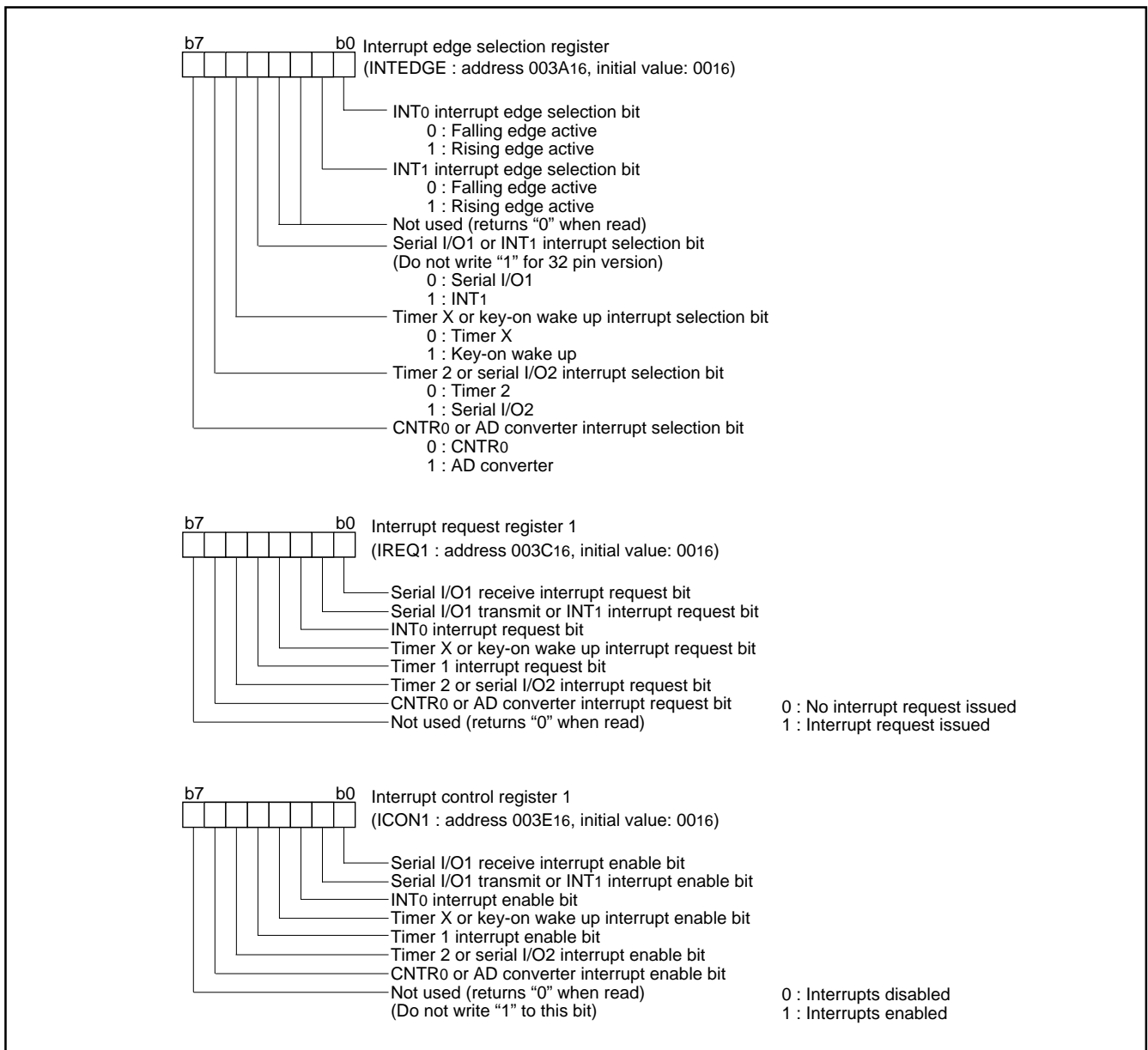


Fig. 18 Structure of Interrupt-related registers

Key Input Interrupt (Key-On Wake-Up)

A key-on wake-up interrupt request is generated by applying "L" level to any pin of port P0 that has been set to input mode.

In other words, it is generated when the AND of input level goes from "1" to "0". An example of using a key input interrupt is shown in Figure 21, where an interrupt request is generated by pressing one of the keys provided as an active-low key matrix which uses ports P00 to P03 as input ports.

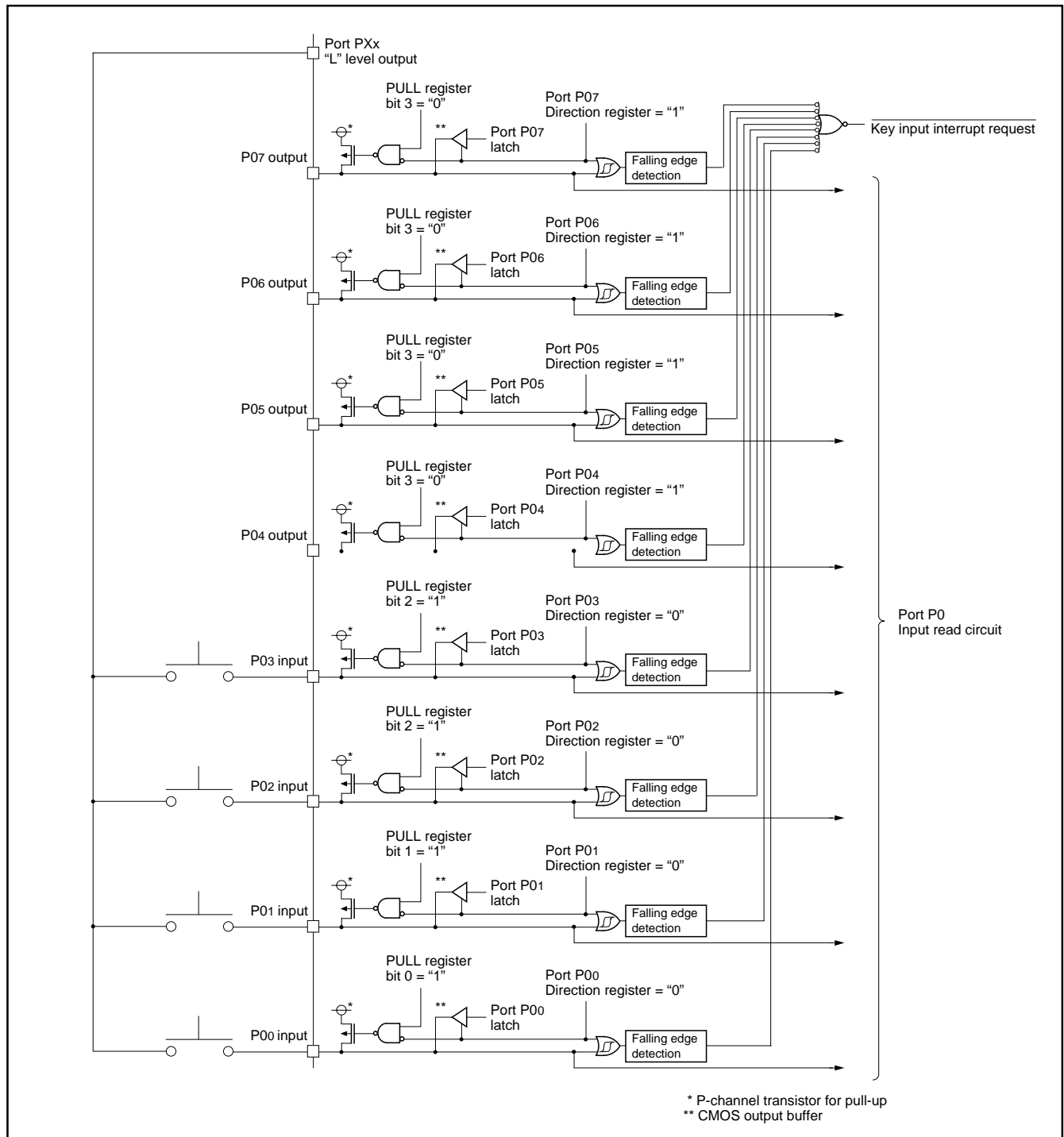


Fig. 19 Connection example when using key input interrupt and port P0 block diagram

Timers

The 7531 Group has 3 timers: timer X, timer 1 and timer 2.

The division ratio of every timer and prescaler is $1/(n+1)$ provided that the value of the timer latch or prescaler is n .

All the timers are down count timers. When a timer reaches "0", an underflow occurs at the next count pulse, and the corresponding timer latch is reloaded into the timer. When a timer underflows, the interrupt request bit corresponding to each timer is set to "1".

●Timer 1, Timer 2

Prescaler 12 always counts $f(X_{IN})/16$. Timer 1 and timer 2 always count the prescaler output and periodically sets the interrupt request bit.

●Timer X

Timer X can be selected in one of 4 operating modes by setting the timer X mode register.

• Timer Mode

The timer counts the signal selected by the timer X count source selection bit.

• Pulse Output Mode

The timer counts the signal selected by the timer X count source selection bit, and outputs a signal whose polarity is inverted each time the timer value reaches "0", from the CNTR₀ pin.

When the CNTR₀ active edge switch bit is "0", the output of the CNTR₀ pin is started with an "H" output.

At "1", this output is started with an "L" output. When using a timer in this mode, set the port P14 direction register to output mode.

• Event Counter Mode

The operation in the event counter mode is the same as that in the timer mode except that the timer counts the input signal from the CNTR₀ pin.

When the CNTR₀ active edge switch bit is "0", the timer counts the rising edge of the CNTR₀ pin. When this bit is "1", the timer counts the falling edge of the CNTR₀ pin.

• Pulse Width Measurement Mode

When the CNTR₀ active edge switch bit is "0", the timer counts the signal selected by the timer X count source selection bit while the CNTR₀ pin is "H". When this bit is "1", the timer counts the signal while the CNTR₀ pin is "L".

In any mode, the timer count can be stopped by setting the timer X count stop bit to "1". Each time the timer overflows, the interrupt request bit is set.

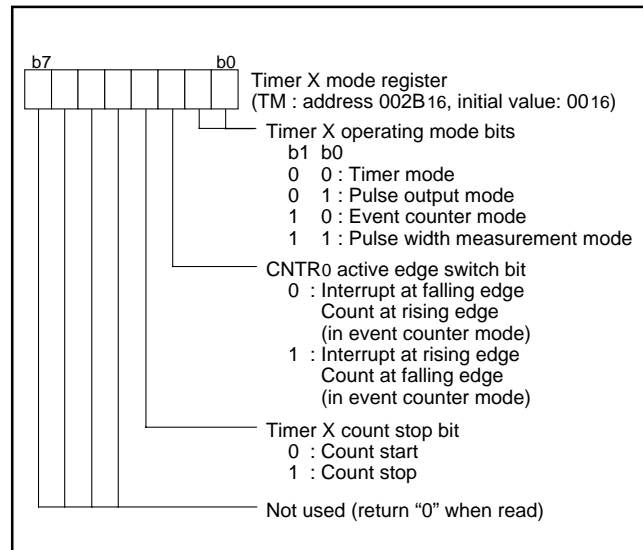


Fig. 20 Structure of timer X mode register

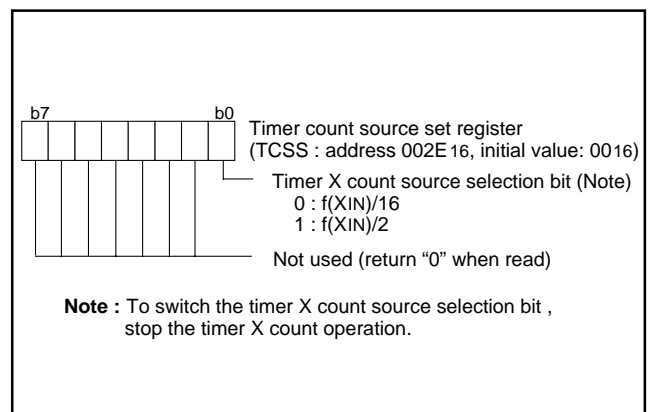


Fig. 21 Timer count source setting register

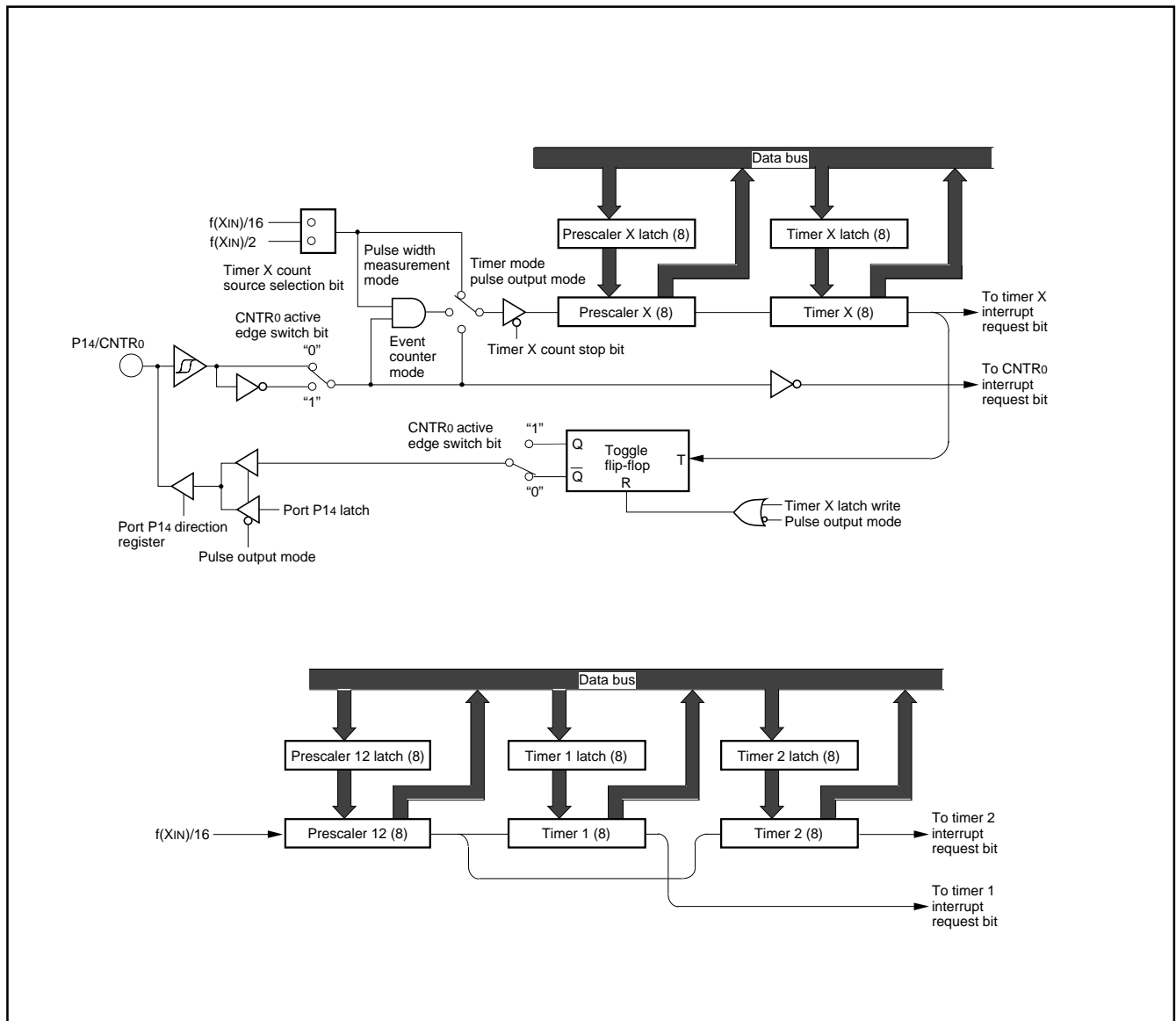


Fig. 22 Block diagram of timer X, timer 1 and timer 2

Serial I/O

Serial I/O1

Serial I/O1 can be used as an asynchronous (UART) serial I/O. A dedicated timer (baud rate generator) is also provided for baud rate generation when serial I/O1 is in operation.

Eight serial data transfer formats can be selected, and the transfer formats to be used by a transmitter and a receiver must be identical. Each of the transmit and receive shift registers has a buffer register (the same address on memory). Since the shift register cannot be written to or read from directly, transmit data is written to the transmit

buffer, and receive data is read from the respective buffer registers. These buffer registers can also hold the next data to be transmitted and receive 2-byte receive data in succession.

By selecting "1" for continuous transmit valid bit (bit 2 of SIO1CON), continuous transmission of the same data is made possible.

This can be used as a simplified PWM.

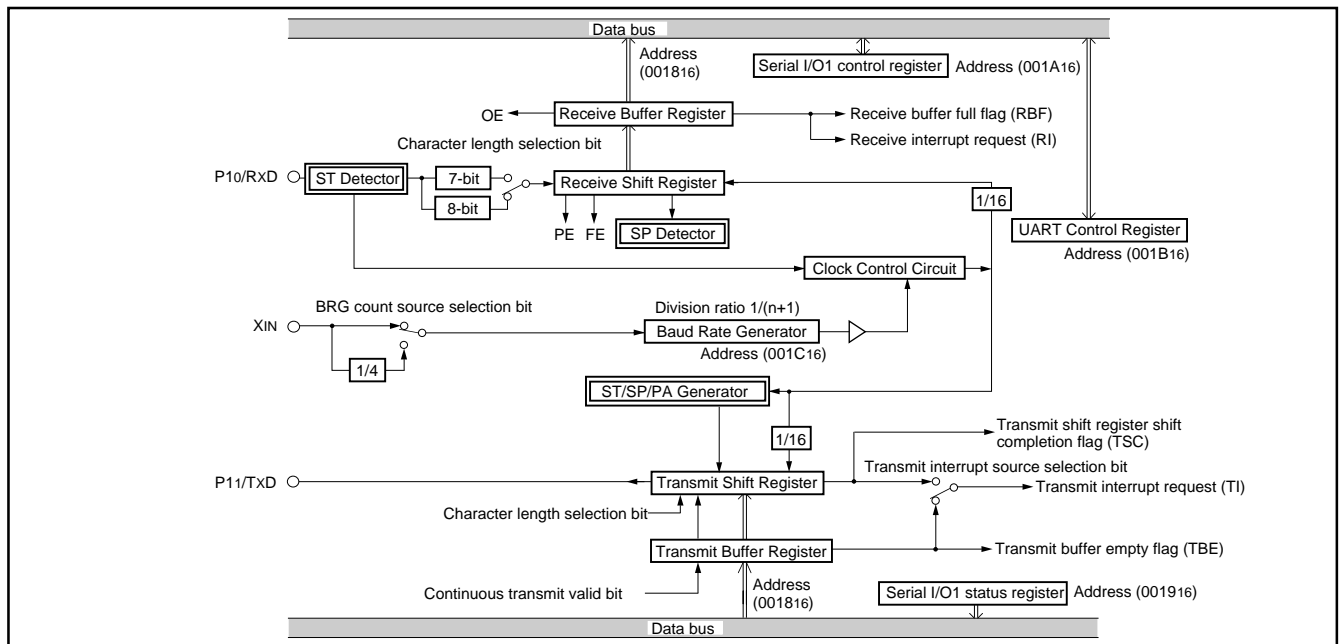


Fig. 23 Block diagram of UART serial I/O

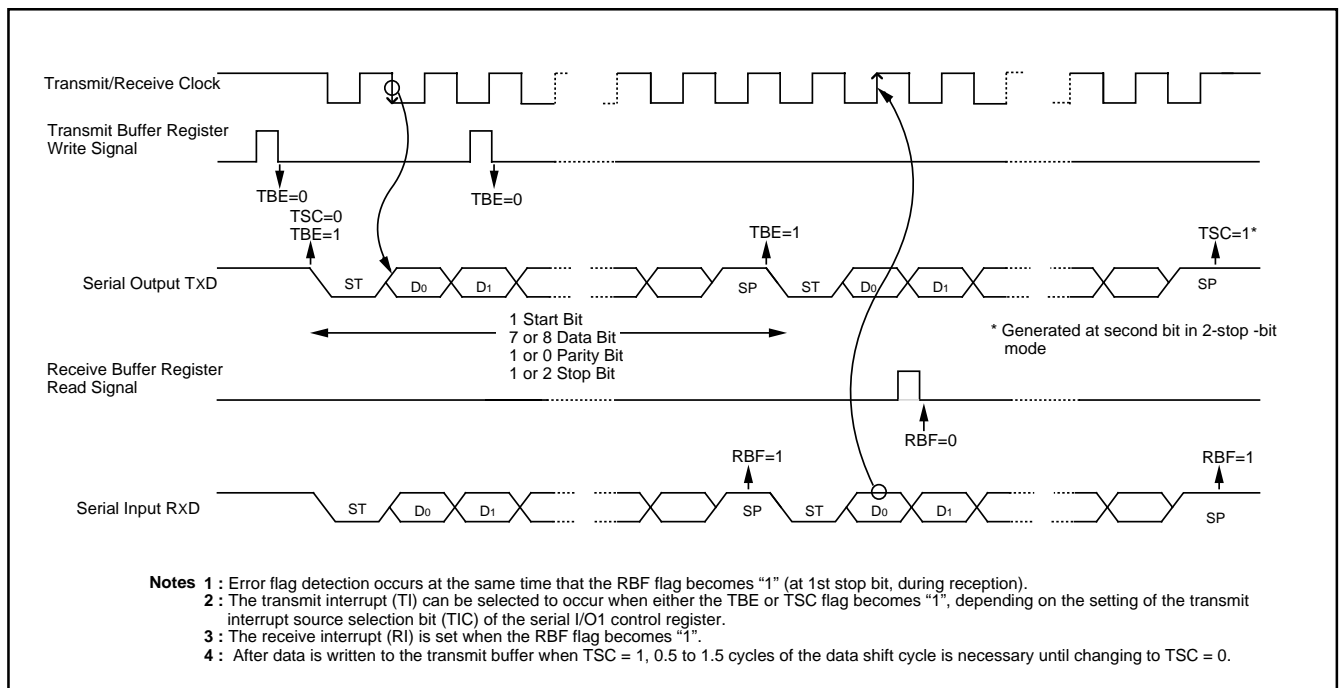


Fig. 24 Operation of UART serial I/O function

[Serial I/O1 control register] SIO1CON

The serial I/O1 control register consists of eight control bits for the serial I/O1 function.

[UART control register] UARTCON

The UART control register consists of four control bits (bits 0 to 3) which are valid when asynchronous serial I/O is selected and set the data format of an data transfer. One bit in this register (bit 4) is always valid and sets the output structure of the P1₁/TxD pin.

[Serial I/O1 status register] SIO1STS

The read-only serial I/O1 status register consists of seven flags (bits 0 to 6) which indicate the operating status of the serial I/O function and various errors.

The receive buffer full flag (bit 1) is cleared to "0" when the receive buffer is read.

If there is an error, it is detected at the same time that data is transferred from the receive shift register to the receive buffer, and the receive buffer full flag is set. A write to the serial I/O1 status register clears all the error flags OE, PE, FE, and SE (bit 3 to bit 6, respectively). Writing "11" to bits 7 and 6 of the serial I/O1 control register initializes this register.

All bits of the serial I/O1 status register are initialized to "81₁₆" at reset.

[Transmit/Receive buffer register] TB/RB

The transmit buffer and the receive buffer are located at the same address. The transmit buffer is write-only and the receive buffer is read-only. If a character bit length is 7-bit, the MSB of data stored in the receive buffer is "0".

[Baud Rate Generator] BRG

The baud rate generator determines the baud rate for serial transfer. The baud rate generator divides the frequency of the count source by $1/(n + 1)$, where n is the value written to the baud rate generator.

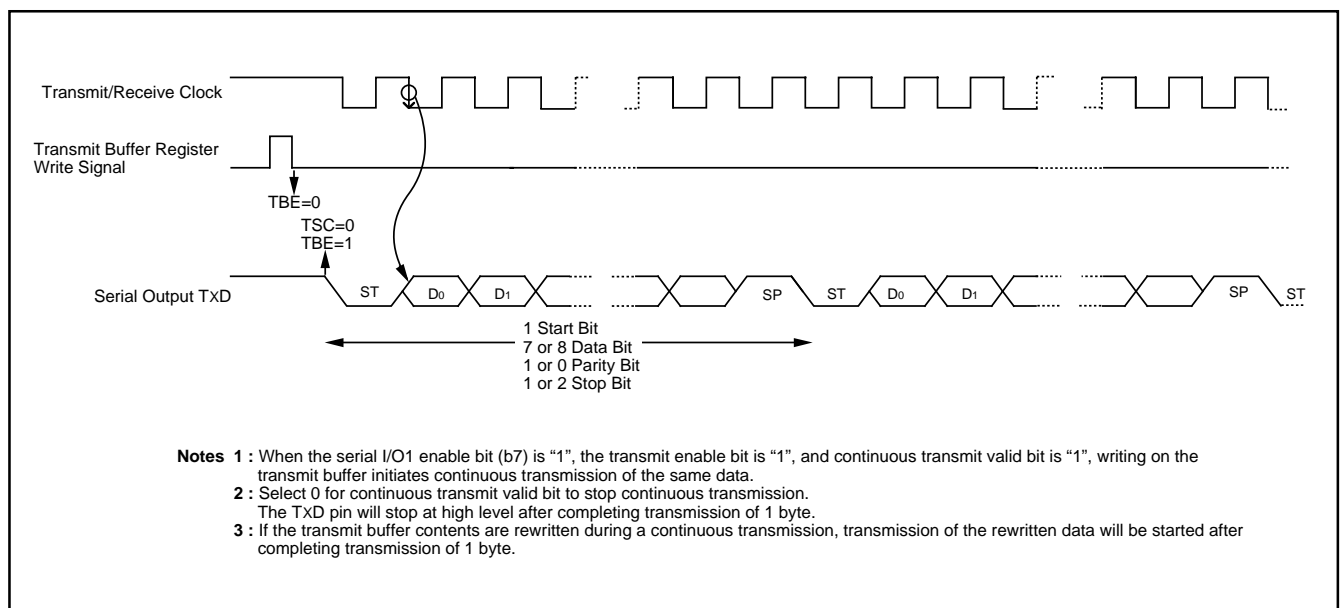


Fig. 25 Continuous transmission operation of UART serial I/O

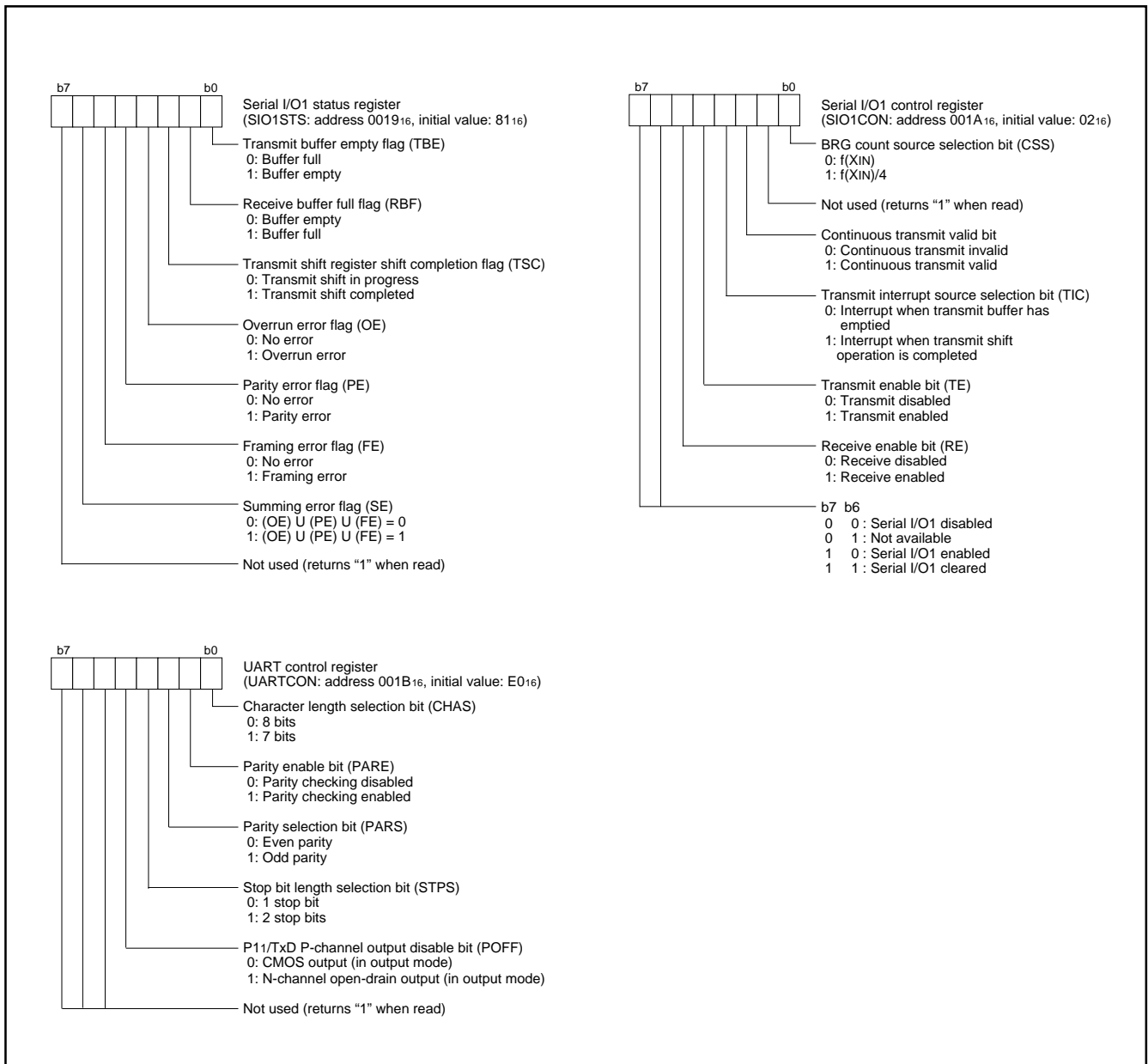


Fig. 26 Structure of serial I/O1-related registers (1)

●Serial I/O2

The serial I/O2 function can be used only for clock synchronous serial I/O.

For clock synchronous serial I/O2 the transmitter and the receiver must use the same clock. When the internal clock is used, transfer is started by a write signal to the serial I/O2 register.

[Serial I/O2 control register] SIO2CON

The serial I/O2 control register contains 8 bits which control various serial I/O functions.

- Set "0" to bit 3 to receive.
- At reception, clear bit 7 to "0" by writing a dummy data to the serial I/O2 register after completion of shift.
- Bit 7 is set to "1" a half cycle (of the shift clock) earlier than completion of shift operation. Accordingly, when using this bit to confirm shift completion, a half cycle or more of the shift clock must pass after confirming that this bit is set to "1", before performing read/write to the serial I/O2 register.

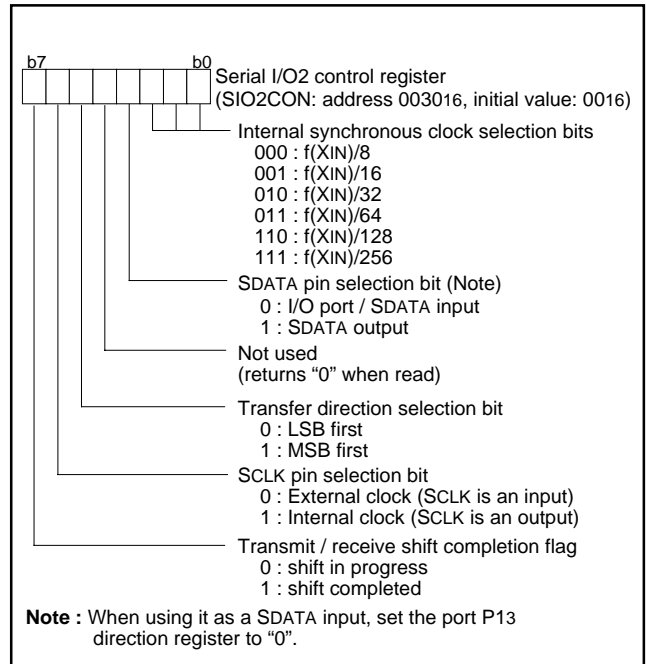


Fig. 27 Structure of serial I/O2 control registers

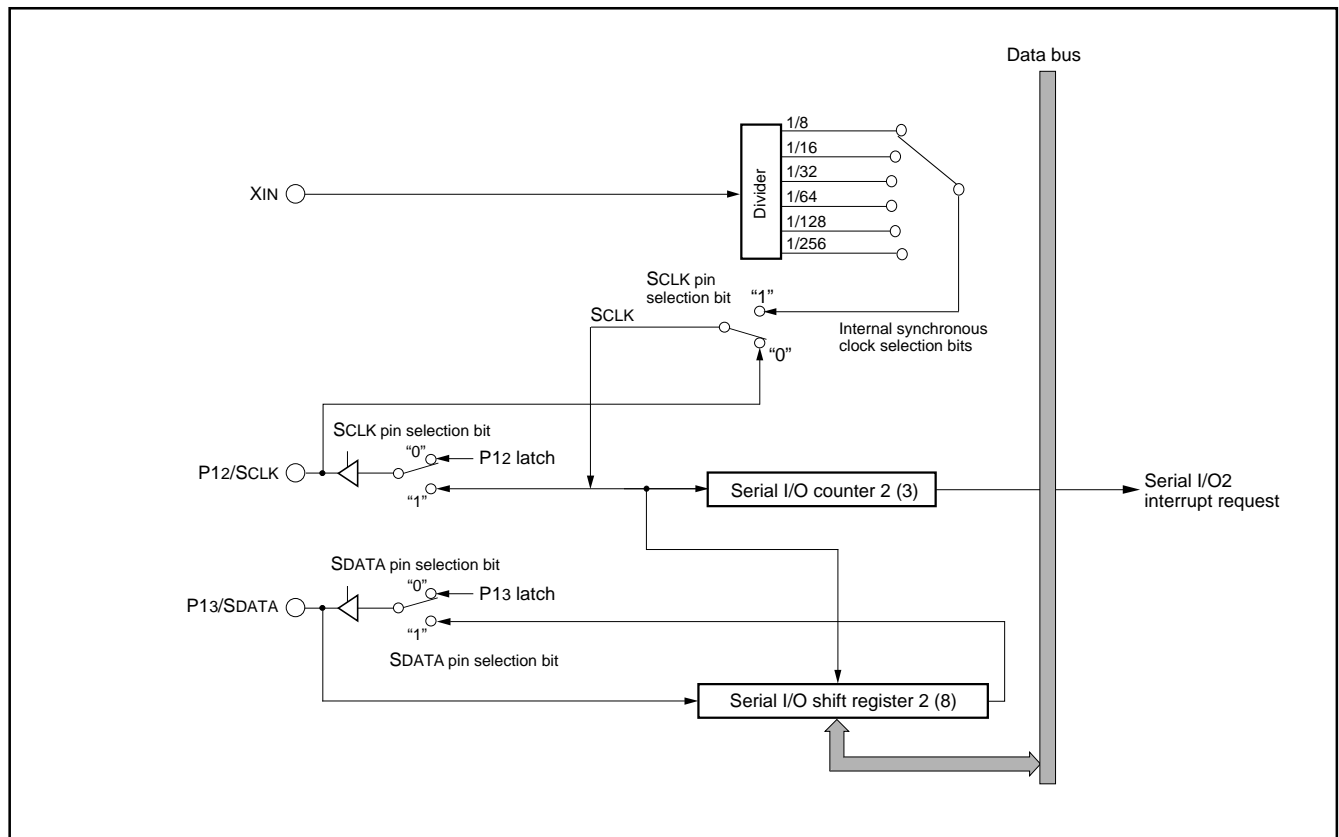


Fig. 28 Block diagram of serial I/O2

Serial I/O2 operation

By writing to the serial I/O2 register (address 0031₁₆) the serial I/O2 counter is set to "7".

After writing, the SDATA pin outputs data every time the transfer clock shifts from a high to a low level. And, as the transfer clock shifts from a low to a high, the SDATA pin reads data, and at the same time the contents of the serial I/O2 register are shifted by 1 bit.

When the internal clock is selected as the transfer clock source, the following operations execute as the transfer clock counts up to 8.

- Serial I/O2 counter is cleared to "0".
- Transfer clock stops at an "H" level.
- Interrupt request bit is set.
- Shift completion flag is set.

Also, the SDATA pin is in a high impedance state after the data transfer is complete (refer to Figure 29).

When the external clock is selected as the transfer clock source, the interrupt request bit is set as the transfer clock counts up to 8, but external control of the clock is required since it does not stop. Notice that the SDATA pin is not in a high impedance state on the completion of data transfer.

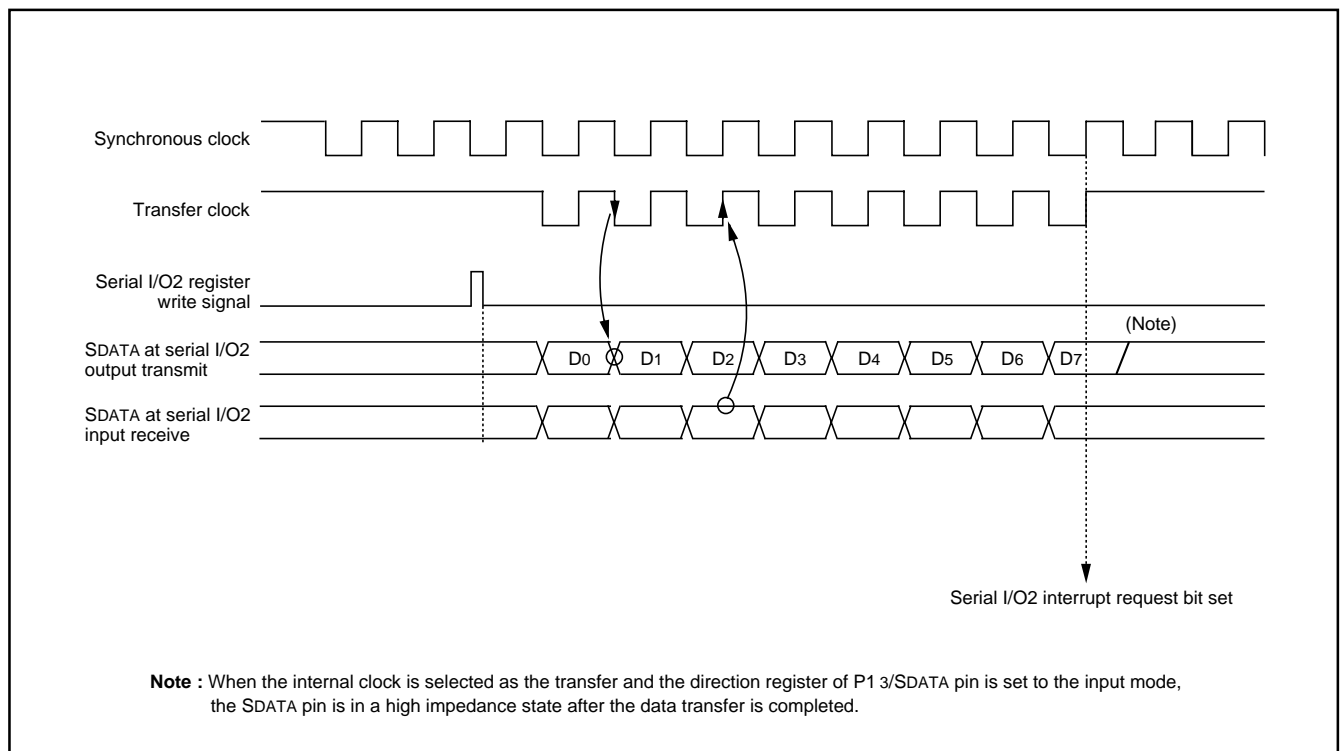


Fig. 29 Serial I/O2 timing (LSB first)

Watchdog Timer

The watchdog timer gives a means for returning to a reset status when the program fails to run on its normal loop due to a runaway. The watchdog timer consists of an 8-bit watchdog timer H and an 8-bit watchdog timer L, being a 16-bit counter.

Standard operation of watchdog timer

The watchdog timer stops when the watchdog timer control register (address 0039₁₆) is not set after reset. Writing an optional value to the watchdog timer control register (address 0039₁₆) causes the watchdog timer to start to count down. When the watchdog timer H underflows, an internal reset occurs. Accordingly, it is programmed that the watchdog timer control register (address 0039₁₆) can be set before an underflow occurs.

When the watchdog timer control register (address 0039₁₆) is read, the values of the high-order 6-bit of the watchdog timer H, STP instruction disable bit and watchdog timer H count source selection bit are read.

Initial value of watchdog timer

By a reset or writing to the watchdog timer control register (address 0039₁₆), the watchdog timer H is set to "FF₁₆" and the watchdog timer L is set to "FF₁₆".

Operation of watchdog timer H count source selection bit

A watchdog timer H count source can be selected by bit 7 of the watchdog timer control register (address 0039₁₆). When this bit is "0", the count source becomes a watchdog timer L underflow signal. The detection time is 131.072 ms at $f(X_{IN})=8$ MHz.

When this bit is "1", the count source becomes $f(X_{IN})/16$. In this case, the detection time is 512 μ s at $f(X_{IN})=8$ MHz.

This bit is cleared to "0" after reset.

Operation of STP instruction disable bit

When the watchdog timer is in operation, the STP instruction can be disabled by bit 6 of the watchdog timer control register (address 0039₁₆).

When this bit is "0", the STP instruction is enabled.

When this bit is "1", the STP instruction is disabled, and an internal reset occurs if the STP instruction is executed.

Once this bit is set to "1", it cannot be changed to "0" by program.

This bit is cleared to "0" after reset.

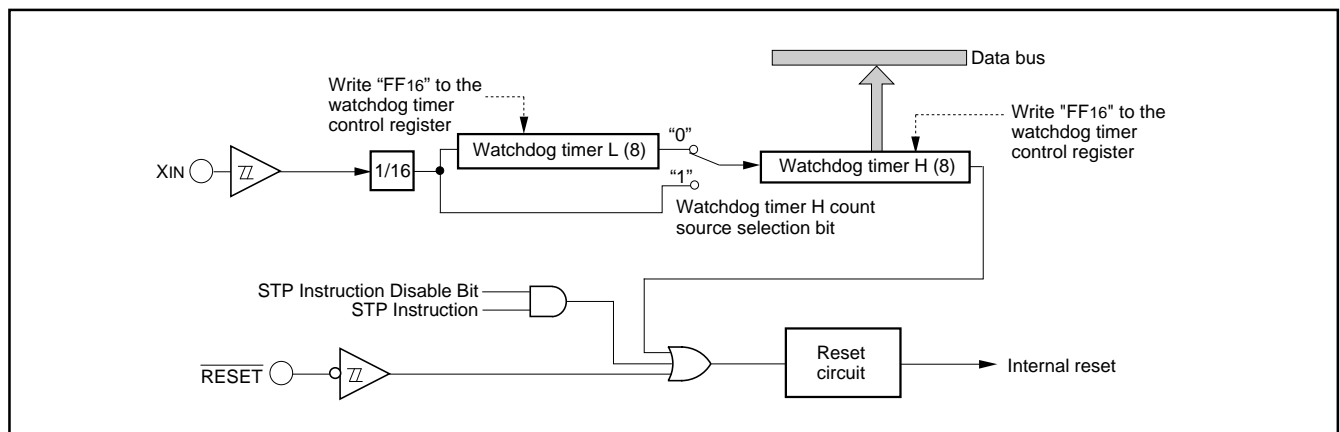


Fig. 33 Block diagram of watchdog timer

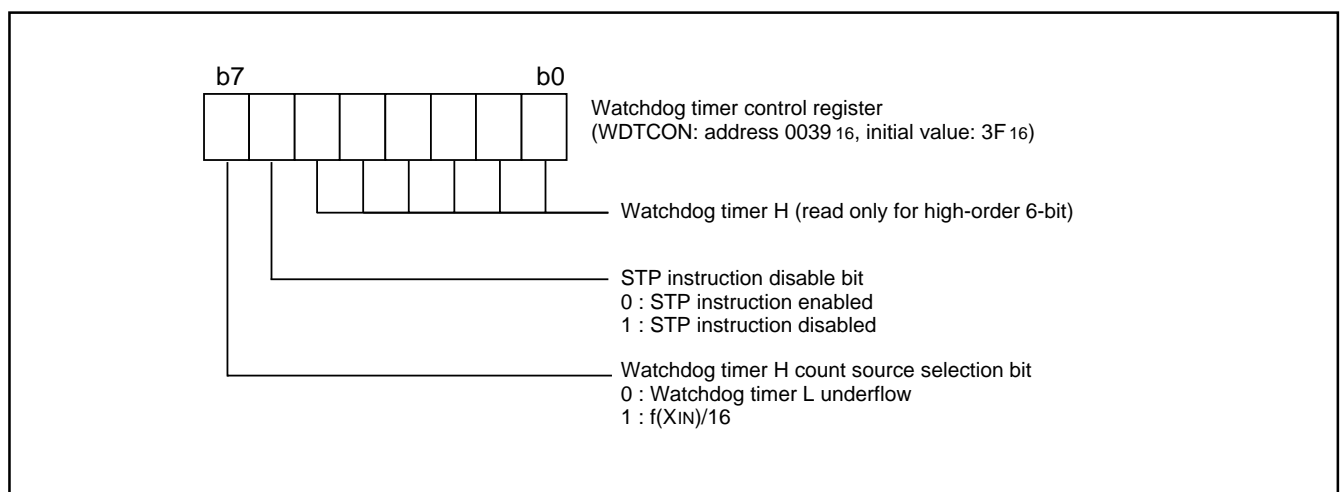


Fig. 34 Structure of watchdog timer control register

Reset Circuit

The microcomputer is put into a reset status by holding the $\overline{\text{RESET}}$ pin at the "L" level for the following interval or more according to the power source voltage and X_{IN} is in stable oscillation.

After that, this reset status is released by returning the $\overline{\text{RESET}}$ pin to the "H" level. The program starts from the address having the contents of address FFFD_{16} as high-order address and the contents of address FFFC_{16} as low-order address.

When $V_{CC} = 2.2$ to 5.5 V, reset input "L" interval is $45\ \mu\text{s}$ or more

When $V_{CC} = 2.4$ to 5.5 V, reset input "L" interval is $35\ \mu\text{s}$ or more

When $V_{CC} = 4.0$ to 5.5 V, reset input "L" interval is $15\ \mu\text{s}$ or more

In the case of $f(\phi) \leq 4$ MHz, the reset input voltage must be 0.8 V or less when the power source voltage passes 4.0 V.

In the case of $f(\phi) \leq 2$ MHz, the reset input voltage must be 0.48 V or less when the power source voltage passes 2.4 V.

In the case of $f(\phi) \leq 1$ MHz, the reset input voltage must be 0.44 V or less when the power source voltage passes 2.2 V.

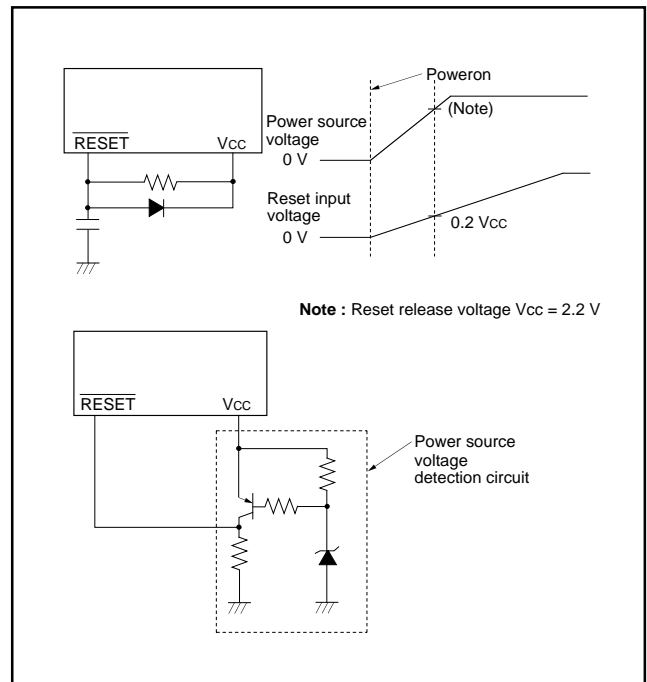


Fig. 35 Example of reset circuit

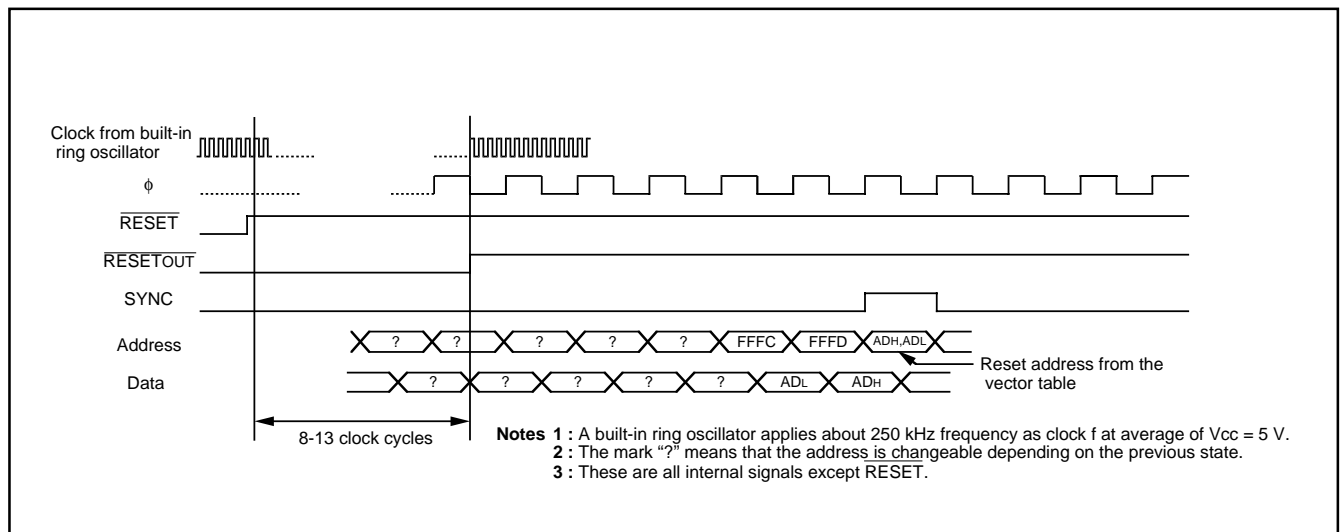


Fig. 36 Timing diagram at reset

	Address	Register contents
(1) Port P0 direction register	0001 ₁₆	00 ₁₆
(2) Port P1 direction register	0003 ₁₆	X X X 0 0 0 0 0
(3) Port P2 direction register	0005 ₁₆	00 ₁₆
(4) Port P3 direction register	0007 ₁₆	00 ₁₆
(5) Pull-up control register	0016 ₁₆	FF ₁₆
(6) Port P1P3 control register	0017 ₁₆	00 ₁₆
(7) Serial I/O1 status register	0019 ₁₆	1 0 0 0 0 0 0 1
(8) Serial I/O1 control register	001A ₁₆	02 ₁₆
(9) UART control register	001B ₁₆	1 1 1 0 0 0 0 0
(10) Prescaler 12	0028 ₁₆	FF ₁₆
(11) Timer 1	0029 ₁₆	01 ₁₆
(12) Timer 2	002A ₁₆	00 ₁₆
(13) Timer X mode register	002B ₁₆	00 ₁₆
(14) Prescaler X	002C ₁₆	FF ₁₆
(15) Timer X	002D ₁₆	FF ₁₆
(16) Timer count source set register	002E ₁₆	00 ₁₆
(17) Serial I/O2 control register	0030 ₁₆	00 ₁₆
(18) A-D control register	0034 ₁₆	10 ₁₆
(19) MISRG	0038 ₁₆	00 ₁₆
(20) Watchdog timer control register	0039 ₁₆	0 0 1 1 1 1 1 1
(21) Interrupt edge selection register	003A ₁₆	00 ₁₆
(22) CPU mode register	003B ₁₆	1 0 0 0 0 0 0 0
(23) Interrupt request register 1	003C ₁₆	00 ₁₆
(24) Interrupt control register 1	003E ₁₆	00 ₁₆
(25) Processor status register	(PS)	X X X X X 1 X X
(26) Program counter	(PC _H)	Contents of address FFFD ₁₆
	(PC _L)	Contents of address FFFC ₁₆

Note X : Undefined

Fig. 37 Internal status of microcomputer at reset

Clock Generating Circuit

An oscillation circuit can be formed by connecting a resonator between X_{IN} and X_{OUT} , and an RC oscillation circuit can be formed by connecting a resistor and a capacitor.

Use the circuit constants in accordance with the resonator manufacturer's recommended values. No external resistor is needed between X_{IN} and X_{OUT} since a feed-back resistor exists on-chip.

Set the constants of the resistor and capacitor when an RC oscillator is used, so that a frequency variation due to LSI variation and resistor and capacitor variations may not exceed the standard input frequency.

●Oscillation control

• Stop mode

When the STP instruction is executed, the internal clock f stops at an "H" level and the X_{IN} oscillator stops. At this time, timer 1 is set to "0116" and prescaler 12 is set to "FF16" when the oscillation stabilization time set bit after release of the STP instruction is "0". On the other hand, timer 1 and prescaler 12 are not set when the above bit is "1". Accordingly, set the wait time fit for the oscillation stabilization time of the oscillator to be used. $f(X_{IN})/16$ is forcibly connected to the input of prescaler 12. When an external interrupt is accepted, oscillation is restarted but the internal clock f remains at "H" until timer 1 underflows. As soon as timer 1 underflows, the internal clock f is supplied. This is because when a ceramic oscillator is used, some time is required until a start of oscillation. In case oscillation is restarted by reset, no wait time is generated. So apply an "L" level to the \overline{RESET} pin while oscillation becomes stable.

• Wait mode

If the WIT instruction is executed, the internal clock f stops at an "H" level, but the oscillator does not stop. The internal clock restarts if a reset occurs or when an interrupt is received. Since the oscillator does not stop, normal operation can be started immediately after the clock is restarted. To ensure that interrupts will be received to release the STP or WIT state, interrupt enable bits must be set to "1" before the STP or WIT instruction is executed.

When the STP status is released, prescaler 12 and timer 1 will start counting clock which is X_{IN} divided by 16, so set the timer 1 interrupt enable bit to "0" before the STP instruction is executed.

Note

For use with the oscillation stabilization set bit after release of the STP instruction set to "1", set values in timer 1 and prescaler 12 after fully appreciating the oscillation stabilization time of the oscillator to be used.

●Switch of ceramic and RC oscillations

After releasing reset the operation starts by starting a built-in ring oscillator. Then, a ceramic oscillation or an RC oscillation is selected by setting bit 5 of the CPU mode register.

The bit 5 can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

●Double-speed mode

When a ceramic oscillation is selected, a double-speed mode can be used. Do not use it when an RC oscillation is selected.

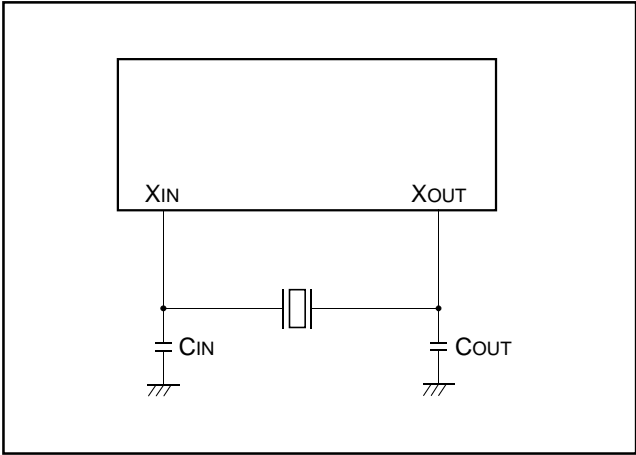


Fig. 38 External circuit of ceramic resonator

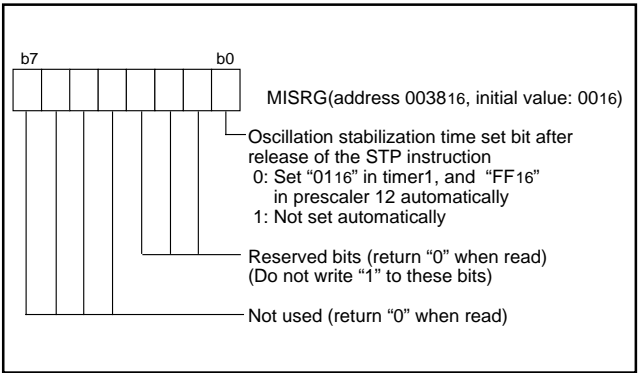


Fig. 41 Structure of MISRG

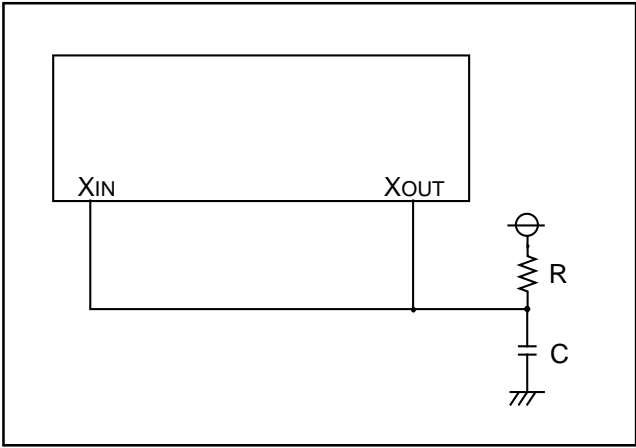


Fig. 39 External circuit of RC oscillation

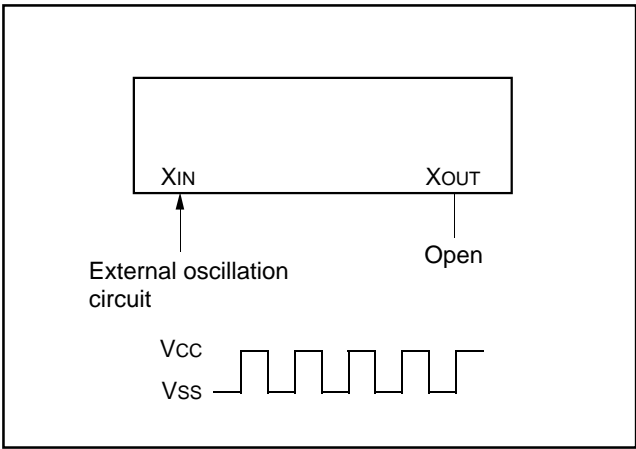


Fig. 40 External clock input circuit

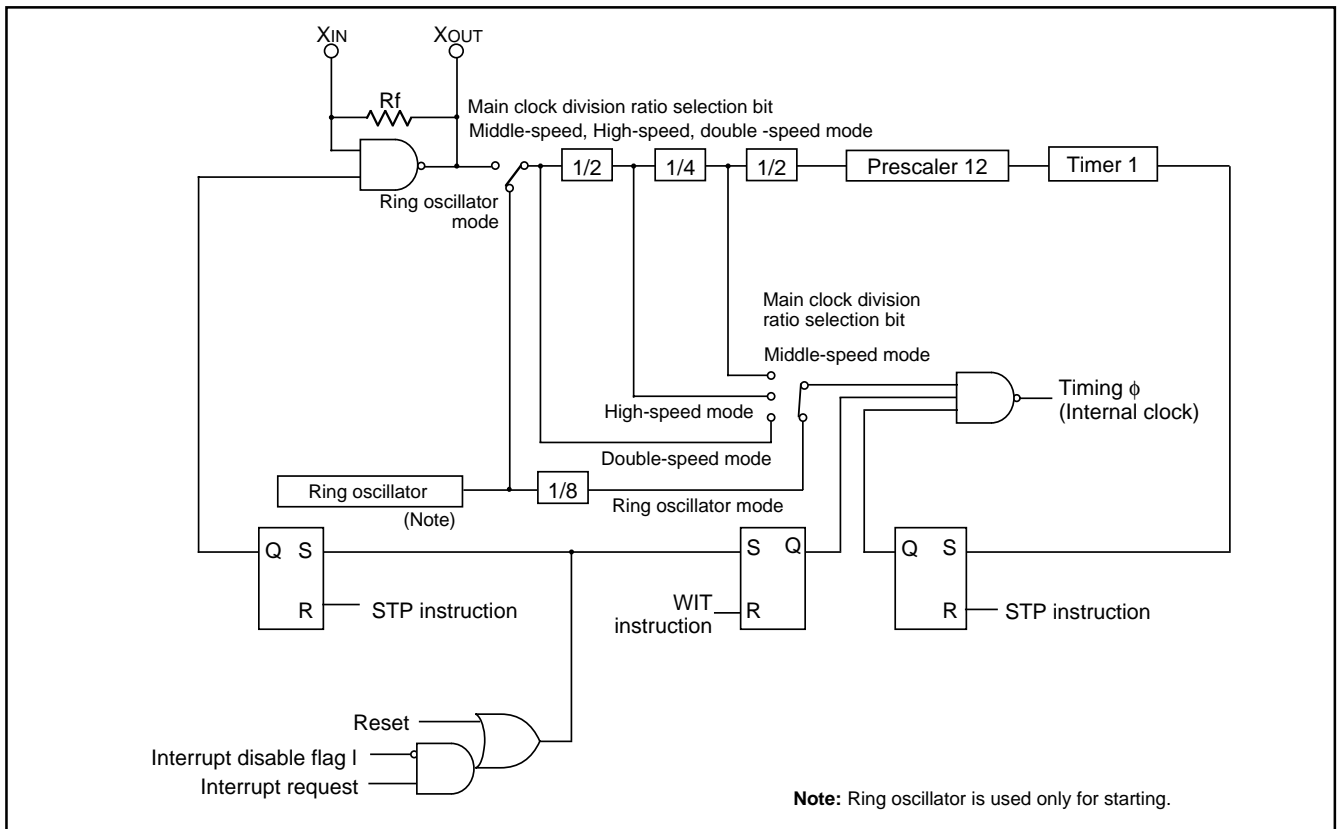


Fig. 42 Block diagram of internal clock generating circuit (for ceramic resonator)

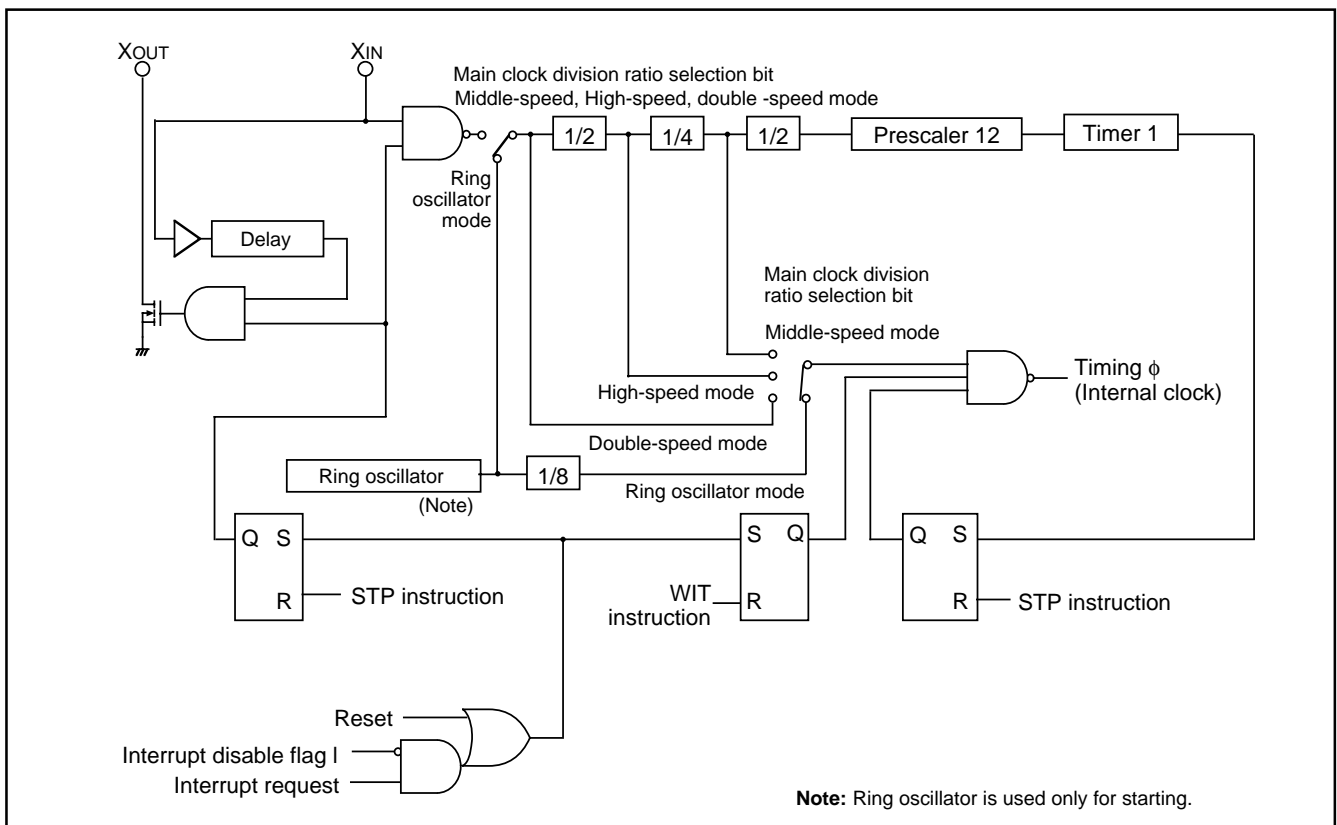


Fig. 43 Block diagram of internal clock generating circuit (for RC oscillation)

NOTES ON PROGRAMMING

Processor Status Register

The contents of the processor status register (PS) after reset are undefined except for the interrupt disable flag I which is "1". After reset, initialize flags which affect program execution. In particular, it is essential to initialize the T flag and the D flag because of their effect on calculations.

Interrupts

The contents of the interrupt request bit do not change even if the BBC or BBS instruction is executed immediately after they are changed by program because this instruction is executed for the previous contents. For executing the instruction for the changed contents, execute one instruction before executing the BBC or BBS instruction.

Decimal Calculations

- For calculations in decimal notation, set the decimal mode flag D to "1", then execute the ADC instruction or SBC instruction. In this case, execute SEC instruction, CLC instruction or CLD instruction after executing one instruction before the ADC instruction or SBC instruction.
- In the decimal mode, the values of the N (negative), V (overflow) and Z (zero) flags are invalid.

Timers

- When n (0 to 255) is written to a timer latch, the frequency division ratio is $1/(n+1)$.
- When a count source of timer X is switched, stop a count of timer X.

Ports

- The values of the port direction registers cannot be read.
That is, it is impossible to use the LDA instruction, memory operation instruction when the T flag is "1", addressing mode using direction register values as qualifiers, and bit test instructions such as BBC and BBS.
It is also impossible to use bit operation instructions such as CLB and SEB and read/modify/write instructions of direction registers for calculations such as ROR.
For setting direction registers, use the LDM instruction, STA instruction, etc.
- Set "1" to each bit 6 of the port P3 direction register and the port P3 register.

A-D Converter

The comparator uses internal capacitors whose charge will be lost if the clock frequency is too low.
Make sure that $f(X_{IN})$ is 500kHz or more during A-D conversion.
Do not execute the STP instruction during A-D conversion.

Instruction Execution Timing

The instruction execution time can be obtained by multiplying the frequency of the internal clock ϕ by the number of cycles mentioned in the machine-language instruction table.

The frequency of the internal clock ϕ is the same as that of the X_{IN} in double-speed mode, twice the X_{IN} cycle in high-speed mode and 8 times the X_{IN} cycle in middle-speed mode.

CPU Mode Register

The oscillation mode selection bit can be rewritten only once after releasing reset. However, after rewriting it is disable to write any value to the bit.

When a ceramic oscillation is selected, a double-speed mode of the clock division ratio selection bits can be used. Do not use it when an RC oscillation is selected.

NOTES ON USE

Handling of Power Source Pin

In order to avoid a latch-up occurrence, connect a capacitor suitable for high frequencies as bypass capacitor between power source pin (V_{CC} pin) and GND pin (V_{SS} pin). Besides, connect the capacitor to as close as possible. For bypass capacitor which should not be located too far from the pins to be connected, a ceramic capacitor of 0.01 μF to 0.1 μF is recommended.

One Time PROM Version

The CNV_{SS} pin is connected to the internal memory circuit block by a low-ohmic resistance, since it has the multiplexed function to be a programmable power source pin (V_{PP} pin) as well.

To improve the noise reduction, connect a track between CNV_{SS} pin and V_{SS} pin with 1 to 10 k Ω resistance.

The mask ROM version track of CNV_{SS} pin has no operational interference even if it is connected via a resistor.

DATA REQUIRED FOR MASK ORDERS

The following are necessary when ordering a mask ROM production:

- (1) Mask ROM Order Confirmation Form
- (2) Mark Specification Form
- (3) Data to be written to ROM, in EPROM form
(three identical copies)

DATA REQUIRED FOR ROM PROGRAMMING ORDERS

The following are necessary when ordering a ROM writing:

- (1) ROM Programming Confirmation Form
- (2) Mark Specification Form (for Special Mark)
- (3) Data to be written to ROM, in EPROM form
(three identical copies)

ROM PROGRAMMING METHOD

The built-in PROM of the blank One Time PROM version can be read or programmed with a general-purpose PROM programmer using a special programming adapter. Set the address of PROM programmer in the user ROM area.

Table 7 Special programming adapter

Package	Name of Programming Adapter
32P4B	PCA7435SP
32P6B-A	PCA7435GP
36P2R-A	PCA7435FP

The PROM of the blank One Time PROM version is not tested or screened in the assembly process and following processes. To ensure proper operation after programming, the procedure shown in Figure 44 is recommended to verify programming.

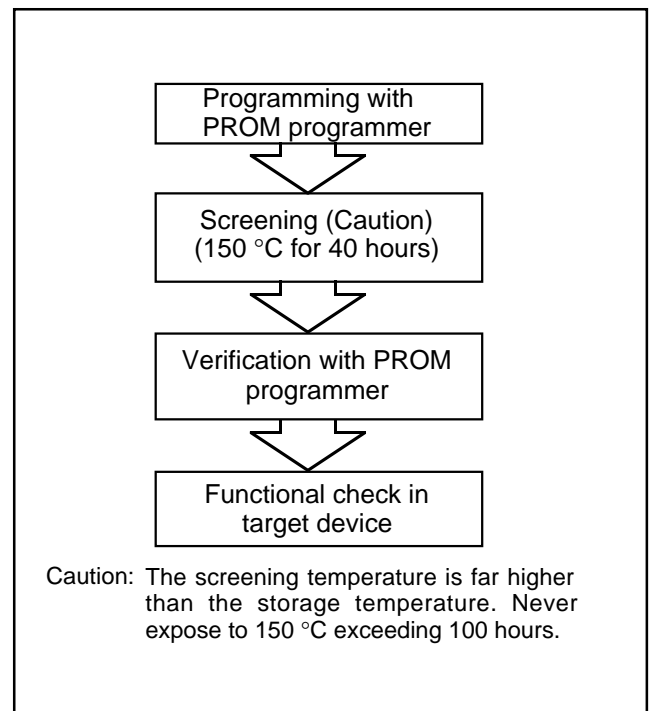


Fig. 44 Programming and testing of One Time PROM version

ELECTRICAL CHARACTERISTICS

(1) 7531 Group (General purpose)

Applied to: M37531M4-XXXFP/SP/GP, M37531M8-XXXFP/SP/GP, M37531E4FP/SP/GP, M37531E8FP/SP

Table 8 Absolute maximum ratings

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Power source voltage	All voltages are based on V _{SS} . Output transistors are cut off.	−0.3 to 7.0	V
V _I	Input voltage P00–P07, P10–P14, P20–P27, P30–P37, V _{REF}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage $\overline{\text{RESET}}$, X _{IN}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage CNV _{SS} (Note 1)		−0.3 to 13	V
V _O	Output voltage P00–P07, P10–P14, P20–P27, P30–P37, X _{OUT}		−0.3 to V _{CC} + 0.3	V
P _d	Power dissipation	T _a = 25°C	300 (Note 2)	mW
T _{opr}	Operating temperature		−20 to 85	°C
T _{stg}	Storage temperature		−40 to 125	°C

Note 1: It is a rating only for the One Time PROM version. Connect to V_{SS} for the mask ROM version.

2: 200 mW for the 32P6B package product.

Table 9 Recommended operating conditions (1)

(V_{CC} = 2.2 to 5.5 V, T_a = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
V _{CC}	Power source voltage (ceramic)	f(X _{IN}) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(X _{IN}) = 2 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	V
		f(X _{IN}) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
		f(X _{IN}) = 1 MHz (Double-speed mode)	2.2	5.0	5.5	V
	Power source voltage (CR)	f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(X _{IN}) = 1 MHz (High-, Middle-speed mode)	2.2	5.0	5.5	V
V _{SS}	Power source voltage			0		V
V _{REF}	Analog reference voltage		2.0		V _{CC}	V
V _{IH}	"H" input voltage	P00–P07, P10–P14, P20–P27, P30–P37	0.8V _{CC}		V _{CC}	V
V _{IH}	"H" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	2.0		V _{CC}	V
V _{IH}	"H" input voltage	RESET, X _{IN}	0.8V _{CC}		V _{CC}	V
V _{IL}	"L" input voltage	P00–P07, P10–P14, P20–P27, P30–P37	0		0.3V _{CC}	V
V _{IL}	"L" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	0		0.8	V
V _{IL}	"L" input voltage	RESET, CNV _{SS}	0		0.2V _{CC}	V
V _{IL}	"L" input voltage	X _{IN}	0		0.16V _{CC}	V
ΣI _{OH} (peak)	"H" total peak output current (Note 2)	P00–P07, P10–P14, P20–P27, P30–P37			–80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P30–P36			60	mA
ΣI _{OH} (avg)	"H" total average output current (Note 2)	P00–P07, P10–P14, P20–P27, P30–P37			–40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P30–P36			30	mA

Note 1: V_{CC} = 4.0 to 5.5V

2: The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Table 10 Recommended operating conditions (2)

(Vcc = 2.2 to 5.5 V, Ta = -20 to 85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
IOH(peak)	"H" peak output current (Note 1)	P00-P07, P10-P14, P20-P27, P30-P37			-10	mA
IOL(peak)	"L" peak output current (Note 1)	P00-P07, P10-P14, P20-P27, P37			10	mA
IOL(peak)	"L" peak output current (Note 1)	P30-P36			30	mA
IOH(avg)	"H" average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-5	mA
IOL(avg)	"L" average output current (Note 2)	P00-P07, P10-P14, P20-P27, P37			5	mA
IOL(avg)	"L" average output current (Note 2)	P30-P36			15	mA
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V Double-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V Double-speed mode			2	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.2 to 5.5 V Double-speed mode			1	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	Vcc = 2.2 to 5.5 V High-, Middle-speed mode			2	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz
	Oscillation frequency (Note 3) at RC oscillation	Vcc = 2.2 to 5.5 V High-, Middle-speed mode			1	MHz

Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current IOL (avg), IOH (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

Table 11 Electrical characteristics

(V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V, T_a = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
VOH	“H” output voltage P00–P07, P10–P14, P20–P27, P30–P37 (Note 1)	I _{OH} = –5 mA V _{CC} = 4.0 to 5.5 V	V _{CC} –1.5			V
		I _{OH} = –1.0 mA V _{CC} = 2.2 to 5.5 V	V _{CC} –1.0			V
VOL	“L” output voltage P00–P07, P10–P14, P20–P27, P37	I _{OL} = 5 mA V _{CC} = 4.0 to 5.5 V			1.5	V
		I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
		I _{OL} = 1.0 mA V _{CC} = 2.2 to 5.5 V			1.0	V
VOL	“L” output voltage P30–P36	I _{OL} = 15 mA V _{CC} = 4.0 to 5.5 V			2.0	V
		I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
		I _{OL} = 10 mA V _{CC} = 2.2 to 5.5 V			1.0	V
VT+–VT–	Hysteresis CNTR0, INT0, INT1 (Note 2) P00–P07 (Note 3)			0.4		V
VT+–VT–	Hysteresis RXD, SCLK, SDATA (Note 2)			0.5		V
VT+–VT–	Hysteresis RESET			0.5		V
I _{IH}	“H” input current P00–P07, P10–P14, P20–P27, P30–P37	V _I = V _{CC} (Pin floating. Pull up transistors “off”)			5.0	μA
I _{IH}	“H” input current RESET	V _I = V _{CC}			5.0	μA
I _{IH}	“H” input current X _{IN}	V _I = V _{CC}		4.0		μA
I _{IL}	“L” input current P00–P07, P10–P14, P20–P27, P30–P37	V _I = V _{SS} (Pin floating. Pull up transistors “off”)			–5.0	μA
I _{IL}	“L” input current RESET, CNV _{SS}	V _I = V _{SS}			–5.0	μA
I _{IL}	“L” input current X _{IN}	V _I = V _{SS}		–4.0		μA
I _{IL}	“L” input current P00–P07, P30–P37	V _I = V _{SS} (Pull up transistors “on”)		–0.2	–0.5	mA
VRAM	RAM hold voltage	When clock stopped	2.0		5.5	V
ICC	Power source current	High-speed mode, f(X _{IN}) = 8 MHz Output transistors “off”		5.0	8.0	mA
		High-speed mode, f(X _{IN}) = 2 MHz, V _{CC} = 2.2 V Output transistors “off”		0.5	1.5	mA
		Double-speed mode, f(X _{IN}) = 4 MHz Output transistors “off”		5.0	8.0	mA
		Middle-speed mode, f(X _{IN}) = 8 MHz Output transistors “off”		2.0	5.0	mA
		f(X _{IN}) = 8 MHz (in WIT state) Functions except timers 1 and 2 stop Output transistors “off”		1.6	3.2	mA
		f(X _{IN}) = 2 MHz, V _{CC} = 2.2 V (in WIT state) Output transistors “off”		0.2		mA
		Increment when A-D conversion is executed f(X _{IN}) = 8 MHz, V _{CC} = 5 V		0.5		mA
		All oscillation stopped (in STP state) Output transistors “off”	T _a = 25 °C T _a = 85 °C	0.1	1.0 10	μA μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is “0”.

2: RXD, SCLK, SDATA, INT0, and INT1 have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to “0” (CMOS level).

3: It is available only when operating key-on wake up.

Table 12 A-D Converter characteristics

(VCC = 2.7 to 5.5 V, VSS = 0 V, Ta = -20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution				10	Bits
—	Linearity error	VCC = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
—	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
VOT	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tCONV	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μA
		VREF = 3.0 V	30	70	120	
II(AD)	A-D port input current				5.0	μA

Table 13 Timing requirements (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _w (RESET)	Reset input “L” pulse width	15			μs
t _c (XIN)	External clock input cycle time	125			ns
t _{WH} (XIN)	External clock input “H” pulse width	50			ns
t _{WL} (XIN)	External clock input “L” pulse width	50			ns
t _c (CNTR)	CNTR ₀ input cycle time	200			ns
t _{WH} (CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input “H” pulse width	80			ns
t _{WL} (CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input “L” pulse width	80			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	1000			ns
t _{WH} (SCLK)	Serial I/O2 clock input “H” pulse width	400			ns
t _{WL} (SCLK)	Serial I/O2 clock input “L” pulse width	400			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time	200			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time	200			ns

Table 14 Timing requirements (2)

(V_{CC} = 2.2 to 5.5 V or 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
t _w (RESET)	Reset input “L” pulse width	V _{CC} = 2.2 to 5.5 V	45			μs
		V _{CC} = 2.4 to 5.5 V	35			μs
t _c (XIN)	External clock input cycle time	V _{CC} = 2.2 to 5.5 V	500			ns
		V _{CC} = 2.4 to 5.5 V	250			ns
t _{WH} (XIN)	External clock input “H” pulse width	V _{CC} = 2.2 to 5.5 V	200			ns
		V _{CC} = 2.4 to 5.5 V	100			ns
t _{WL} (XIN)	External clock input “L” pulse width	V _{CC} = 2.2 to 5.5 V	200			ns
		V _{CC} = 2.4 to 5.5 V	100			ns
t _c (CNTR)	CNTR ₀ input cycle time	V _{CC} = 2.2 to 5.5 V	1000			ns
		V _{CC} = 2.4 to 5.5 V	500			ns
t _{WH} (CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input “H” pulse width	V _{CC} = 2.2 to 5.5 V	460			ns
		V _{CC} = 2.4 to 5.5 V	230			ns
t _{WL} (CNTR)	CNTR ₀ , INT ₀ , INT ₁ , input “L” pulse width	V _{CC} = 2.2 to 5.5 V	460			ns
		V _{CC} = 2.4 to 5.5 V	230			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	V _{CC} = 2.2 to 5.5 V	4000			ns
		V _{CC} = 2.4 to 5.5 V	2000			ns
t _{WH} (SCLK)	Serial I/O2 clock input “H” pulse width	V _{CC} = 2.2 to 5.5 V	1900			ns
		V _{CC} = 2.4 to 5.5 V	950			ns
t _{WL} (SCLK)	Serial I/O2 clock input “L” pulse width	V _{CC} = 2.2 to 5.5 V	1900			ns
		V _{CC} = 2.4 to 5.5 V	950			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time		400			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time		400			ns

Table 15 Switching characteristics (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –20 to 85 °C, unless otherwise noted)

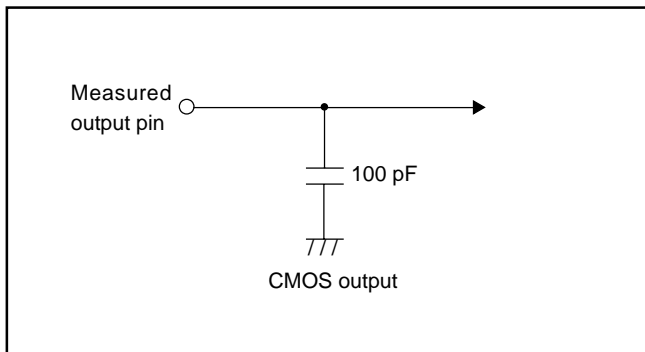
Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _c (SCLK)/2–30			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _c (SCLK)/2–30			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			140	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			30	ns
t _f (SCLK)	Serial I/O2 clock output falling time			30	ns
t _r (CMOS)	CMOS output rising time (Note 1)		10	30	ns
t _f (CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XOUT is excluded.

Table 16 Switching characteristics (2)

(V_{CC} = 2.2 to 5.5 V, V_{SS} = 0 V, T_a = –20 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _c (SCLK)/2–50			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _c (SCLK)/2–50			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			350	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			50	ns
t _f (SCLK)	Serial I/O2 clock output falling time			50	ns
t _r (CMOS)	CMOS output rising time (Note 1)		20	50	ns
t _f (CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin XOUT is excluded.

Fig. 45 Switching characteristics measurement circuit diagram
(General purpose)

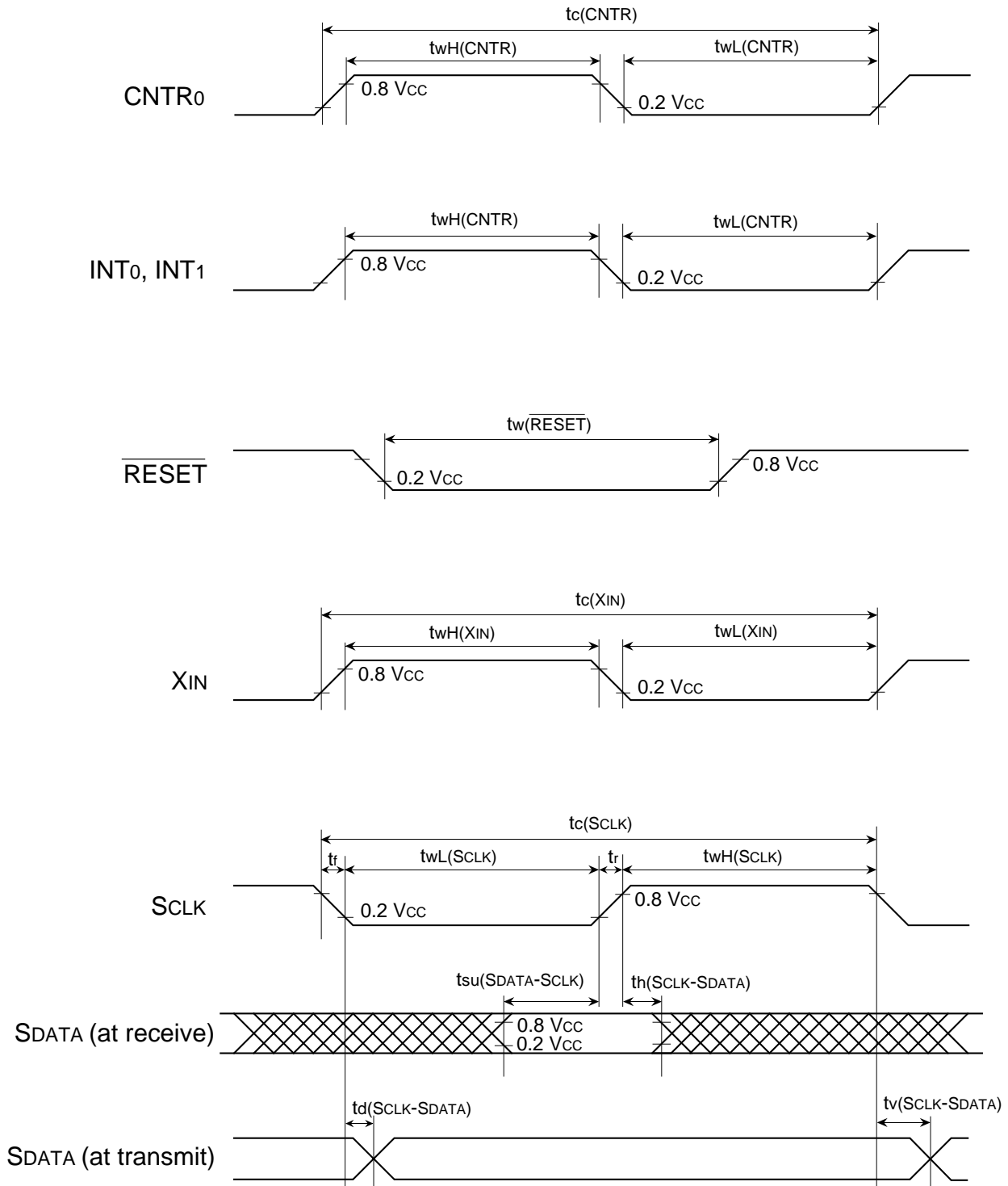


Fig. 46 Timing chart (General purpose)

(2) 7531 Group (Extended operating temperature version)
 Applied to: M37531M4T-XXXFP/SP/GP, M37531E4T-XXXGP

Table 17 Absolute maximum ratings

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Power source voltage	All voltages are based on V _{SS} . Output transistors are cut off.	−0.3 to 7.0	V
V _I	Input voltage P00–P07, P10–P14, P20–P27, P30–P37, V _{REF}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage $\overline{\text{RESET}}$, X _{IN}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage CNV _{SS} (Note 1)		−0.3 to 13	V
V _O	Output voltage P00–P07, P10–P14, P20–P27, P30–P37, X _{OUT}		−0.3 to V _{CC} + 0.3	V
P _d	Power dissipation	T _a = 25°C	300 (Note 2)	mW
T _{opr}	Operating temperature		−40 to 85	°C
T _{stg}	Storage temperature		−65 to 150	°C

Notes 1: It is a rating only for the One Time PROM version. Connect to V_{SS} for the mask ROM version.

2: 200 mW for the 32P6B package version.

Table 18 Recommended operating conditions (1)

(V_{CC} = 2.4 to 5.5 V, T_a = -40 to 85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
V _{CC}	Power source voltage (ceramic)	f(X _{IN}) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(X _{IN}) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
V _{SS}	Power source voltage			0		V
V _{REF}	Analog reference voltage		2.0		V _{CC}	V
V _{IH}	"H" input voltage	P00-P07, P10-P14, P20-P27, P30-P37	0.8V _{CC}		V _{CC}	V
V _{IH}	"H" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	2.0		V _{CC}	V
V _{IH}	"H" input voltage	RESET, X _{IN}	0.8V _{CC}		V _{CC}	V
V _{IL}	"L" input voltage	P00-P07, P10-P14, P20-P27, P30-P37	0		0.3V _{CC}	V
V _{IL}	"L" input voltage (TTL input level selected)	P10, P12, P13, P36, P37 (Note 1)	0		0.8	V
V _{IL}	"L" input voltage	RESET, CNV _{SS}	0		0.2V _{CC}	V
V _{IL}	"L" input voltage	X _{IN}	0		0.16V _{CC}	V
ΣI _{OH} (peak)	"H" total peak output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P00-P07, P10-P14, P20-P27, P37			80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P30-P36			60	mA
ΣI _{OH} (avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P27, P30-P37			-40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P00-P07, P10-P14, P20-P27, P37			40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P30-P36			30	mA

Note 1: V_{CC} = 4.0 to 5.5V

Note 2: The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Table 19 Recommended operating conditions (2)

(V_{CC} = 2.4 to 5.5 V, T_a = –40 to 85 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
I _{OH} (peak)	"H" peak output current (Note 1)	P00–P07, P10–P14, P20–P27, P30–P37			–10	mA
I _{OL} (peak)	"L" peak output current (Note 1)	P00–P07, P10–P14, P20–P27, P37			10	mA
I _{OL} (peak)	"L" peak output current (Note 1)	P30–P36			30	mA
I _{OH} (avg)	"H" average output current (Note 2)	P00–P07, P10–P14, P20–P27, P30–P37			–5	mA
I _{OL} (avg)	"L" average output current (Note 2)	P00–P07, P10–P14, P20–P27, P37			5	mA
I _{OL} (avg)	"L" average output current (Note 2)	P30–P36			15	mA
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 4.0 to 5.5 V Double-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 2.4 to 5.5 V Double-speed mode			2	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	V _{CC} = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	V _{CC} = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz

Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current I_{OL} (avg), I_{OH} (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

Table 20 Electrical characteristics

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 85 °C, unless otherwise noted)

Symbol	Parameter		Test conditions	Limits			Unit
				Min.	Typ.	Max.	
VOH	“H” output voltage P00–P07, P10–P14, P20–P27, P30–P37 (Note 1)		I _{OH} = –5 mA V _{CC} = 4.0 to 5.5 V	V _{CC} –1.5			V
			I _{OH} = –1.0 mA V _{CC} = 2.4 to 5.5 V	V _{CC} –1.0			V
VOL	“L” output voltage P00–P07, P10–P14, P20–P27, P37		I _{OL} = 5 mA V _{CC} = 4.0 to 5.5 V			1.5	V
			I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
			I _{OL} = 1.0 mA V _{CC} = 2.4 to 5.5 V			1.0	V
VOL	“L” output voltage P30–P36		I _{OL} = 15 mA V _{CC} = 4.0 to 5.5 V			2.0	V
			I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
			I _{OL} = 10 mA V _{CC} = 2.4 to 5.5 V			1.0	V
VT+–VT–	Hysteresis	CNTR0, INT0, INT1 (Note 2) P00–P07 (Note 3)			0.4		V
VT+–VT–	Hysteresis	RxD, SCLK, SData (Note 2)			0.5		V
VT+–VT–	Hysteresis	RESET			0.5		V
I _{IH}	“H” input current	P00–P07, P10–P14, P20–P27, P30–P37	V _I = V _{CC} (Pin floating. Pull up transistors “off”)			5.0	μA
I _{IH}	“H” input current	RESET	V _I = V _{CC}			5.0	μA
I _{IH}	“H” input current	XIN	V _I = V _{CC}		4.0		μA
I _{IL}	“L” input current	P00–P07, P10–P14, P20–P27, P30–P37	V _I = V _{SS} (Pin floating. Pull up transistors “off”)			–5.0	μA
I _{IL}	“L” input current	RESET, CNV _{SS}	V _I = V _{SS}			–5.0	μA
I _{IL}	“L” input current	XIN	V _I = V _{SS}		–4.0		μA
I _{IL}	“L” input current	P00–P07, P30–P37	V _I = V _{SS} (Pull up transistors “on”)		–0.2	–0.5	mA
VRAM	RAM hold voltage		When clock stopped	2.0		5.5	V
ICC	Power source current	High-speed mode, f(XIN) = 8 MHz Output transistors “off”			5.0	8.0	mA
		High-speed mode, f(XIN) = 2 MHz, V _{CC} = 2.4 V Output transistors “off”			0.5	1.5	mA
		Double-speed mode, f(XIN) = 4 MHz Output transistors “off”			5.0	8.0	mA
		Middle-speed mode, f(XIN) = 8 MHz, Output transistors “off”			2.0	5.0	mA
		f(XIN) = 8 MHz (in WIT state) Functions except Timer 1 and Timer 2 stop Output transistors “off”			1.6	3.2	mA
		f(XIN) = 2 MHz, V _{CC} = 2.4 V (in WIT state) Output transistors “off”			0.2		mA
		Increment when A-D conversion is executed f(XIN) = 8 MHz, V _{CC} = 5 V			0.5		mA
		All oscillation stopped (in STP state) Output transistors “off”	T _a = 25 °C		0.1	1.0	μA
			T _a = 85 °C			10	μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is “0”.**2:** RxD, SCLK, SData, INT0 and INT1 have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to “0” (CMOS level).**3:** It is available only when operating key-on wake up.

Table 21 A-D Converter characteristics

(VCC = 2.7 to 5.5 V, VSS = 0 V, Ta = -40 to 85 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution				10	Bits
—	Linearity error	VCC = 2.7 to 5.5 V Ta = 25 °C			±3	LSB
—	Differential nonlinear error	VCC = 2.7 to 5.5 V Ta = 25 °C			±0.9	LSB
VOT	Zero transition voltage	VCC = VREF = 5.12 V	0	5	20	mV
		VCC = VREF = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	VCC = VREF = 5.12 V	5105	5115	5125	mV
		VCC = VREF = 3.072 V	3060	3069	3075	mV
tCONV	Conversion time				122	tc(XIN)
RLADDER	Ladder resistor			55		kΩ
IVREF	Reference power source input current	VREF = 5.0 V	50	150	200	μA
		VREF = 3.0 V	30	70	120	
II(AD)	A-D port input current				5.0	μA

Table 22 Timing requirements (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _w (RESET)	Reset input “L” pulse width	15			μs
t _c (XIN)	External clock input cycle time	125			ns
t _{WH} (XIN)	External clock input “H” pulse width	50			ns
t _{WL} (XIN)	External clock input “L” pulse width	50			ns
t _c (CNTR)	CNTR0 input cycle time	200			ns
t _{WH} (CNTR)	CNTR0, INT0, INT1 input “H” pulse width	80			ns
t _{WL} (CNTR)	CNTR0, INT0, INT1 input “L” pulse width	80			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	1000			ns
t _{WH} (SCLK)	Serial I/O2 clock input “H” pulse width	400			ns
t _{WL} (SCLK)	Serial I/O2 clock input “L” pulse width	400			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time	200			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time	200			ns

Table 23 Timing requirements (2)

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _w (RESET)	Reset input “L” pulse width	35			μs
t _c (XIN)	External clock input cycle time	250			ns
t _{WH} (XIN)	External clock input “H” pulse width	100			ns
t _{WL} (XIN)	External clock input “L” pulse width	100			ns
t _c (CNTR)	CNTR0 input cycle time	500			ns
t _{WH} (CNTR)	CNTR0, INT0, INT1 input “H” pulse width	230			ns
t _{WL} (CNTR)	CNTR0, INT0, INT1 input “L” pulse width	230			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	2000			ns
t _{WH} (SCLK)	Serial I/O2 clock input “H” pulse width	950			ns
t _{WL} (SCLK)	Serial I/O2 clock input “L” pulse width	950			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time	400			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time	400			ns

Table 24 Switching characteristics (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 85 °C, unless otherwise noted)

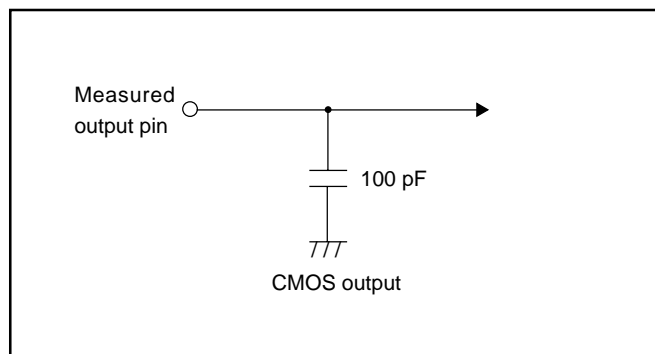
Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _c (SCLK)/2–30			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _c (SCLK)/2–30			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			140	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			30	ns
t _f (SCLK)	Serial I/O2 clock output falling time			30	ns
t _r (CMOS)	CMOS output rising time (Note 1)		10	30	ns
t _f (CMOS)	CMOS output falling time (Note 1)		10	30	ns

Note 1: Pin XOUT is excluded.

Table 25 Switching characteristics (2)

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 85 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _c (SCLK)/2–50			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _c (SCLK)/2–50			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			350	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			50	ns
t _f (SCLK)	Serial I/O2 clock output falling time			50	ns
t _r (CMOS)	CMOS output rising time (Note 1)		20	50	ns
t _f (CMOS)	CMOS output falling time (Note 1)		20	50	ns

Note 1: Pin XOUT is excluded.

Fig. 47 Switching characteristics measurement circuit diagram
(Extended operating temperature version)

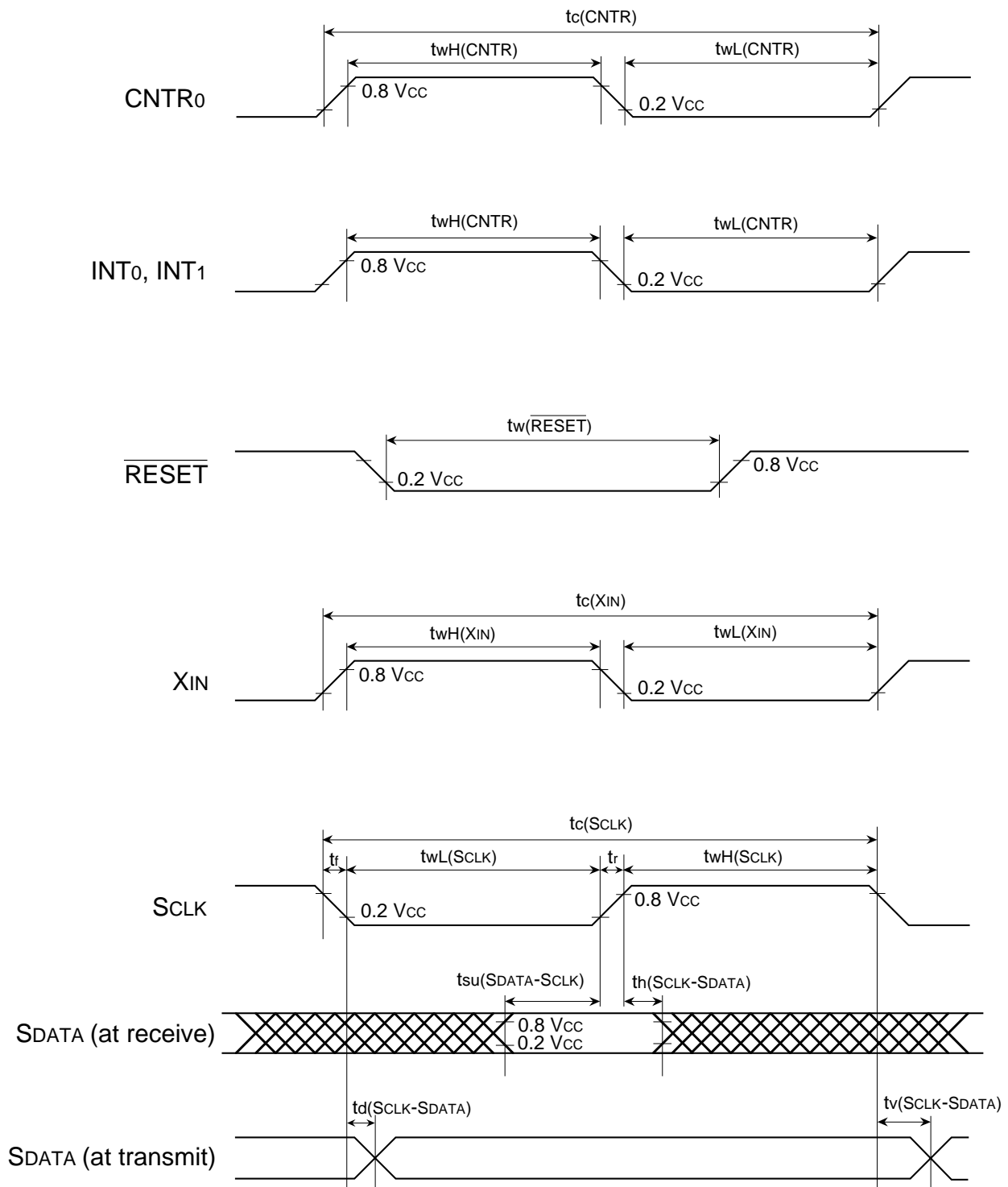


Fig. 48 Timing chart (Extended operating temperature version)

(3) 7531 Group (Extended operating temperature 125 °C version)
Applied to: M37531M4V-XXXGP, M37531E4V-XXXGP

Table 26 Absolute maximum ratings

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Power source voltage	All voltages are based on V _{SS} . Output transistors are cut off.	−0.3 to 7.0	V
V _I	Input voltage P00–P07, P10–P14, P20–P25, P30–P34, P37, V _{REF}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage $\overline{\text{RESET}}$, X _{IN}		−0.3 to V _{CC} + 0.3	V
V _I	Input voltage CNV _{SS} (Note 1)		−0.3 to 13	V
V _O	Output voltage P00–P07, P10–P14, P20–P25, P30–P34, P37, X _{OUT}		−0.3 to V _{CC} + 0.3	V
P _d	Power dissipation	T _a = 25°C	200	mW
T _{opr}	Operating temperature (Note 2)		−40 to 125	°C
T _{stg}	Storage temperature		−65 to 150	°C

Notes 1: It is a rating only for the One Time PROM version. Connect to V_{SS} for the mask ROM version.

2: The total time is limited as follows:
6000 hours at 55 to 85 °C, 1000 hours at 85 to 125 °C

Table 27 Recommended operating conditions (1)
(V_{CC} = 2.4 to 5.5 V, T_a = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
V _{CC}	Power source voltage (ceramic)	f(X _{IN}) = 8 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
		f(X _{IN}) = 4 MHz (Double-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (Double-speed mode)	2.4	5.0	5.5	V
	Power source voltage (CR)	f(X _{IN}) = 4 MHz (High-, Middle-speed mode)	4.0	5.0	5.5	V
		f(X _{IN}) = 2 MHz (High-, Middle-speed mode)	2.4	5.0	5.5	V
V _{SS}	Power source voltage			0		V
V _{REF}	Analog reference voltage		2.0		V _{CC}	V
V _{IH}	"H" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0.8V _{CC}		V _{CC}	V
V _{IH}	"H" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)	2.0		V _{CC}	V
V _{IH}	"H" input voltage	RESET, X _{IN}	0.8V _{CC}		V _{CC}	V
V _{IL}	"L" input voltage	P00-P07, P10-P14, P20-P25, P30-P34, P37	0		0.3V _{CC}	V
V _{IL}	"L" input voltage (TTL input level selected)	P10, P12, P13, P37 (Note 1)	0		0.8	V
V _{IL}	"L" input voltage	RESET, CNV _{SS}	0		0.2V _{CC}	V
V _{IL}	"L" input voltage	X _{IN}	0		0.16V _{CC}	V
ΣI _{OH} (peak)	"H" total peak output current (Note 2)	P00-P07, P10-P14, P20-P25, P30-P34, P37			-80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P00-P07, P10-P14, P20-P25, P37			80	mA
ΣI _{OL} (peak)	"L" total peak output current (Note 2)	P30-P34			60	mA
ΣI _{OH} (avg)	"H" total average output current (Note 2)	P00-P07, P10-P14, P20-P25, P30-P34, P37			-40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P00-P07, P10-P14, P20-P25, P37			40	mA
ΣI _{OL} (avg)	"L" total average output current (Note 2)	P30-P34			30	mA

Note 1: V_{CC} = 4.0 to 5.5V

2: The total output current is the sum of all the currents flowing through all the applicable ports. The total average current is an average value measured over 100 ms. The total peak current is the peak value of all the currents.

Table 28 Recommended operating conditions (2)

(V_{CC} = 2.4 to 5.5 V, T_a = –40 to 125 °C, unless otherwise noted)

Symbol	Parameter		Limits			Unit
			Min.	Typ.	Max.	
I _{OH} (peak)	"H" peak output current (Note 1)	P00–P07, P10–P14, P20–P25, P30–P34, P37			–10	mA
I _{OL} (peak)	"L" peak output current (Note 1)	P00–P07, P10–P14, P20–P25, P37			10	mA
I _{OL} (peak)	"L" peak output current (Note 1)	P30–P34			30	mA
I _{OH} (avg)	"H" average output current (Note 2)	P00–P07, P10–P14, P20–P25, P30–P34, P37			–5	mA
I _{OL} (avg)	"L" average output current (Note 2)	P00–P07, P10–P14, P20–P25, P37			5	mA
I _{OL} (avg)	"L" average output current (Note 2)	P30–P34			15	mA
f(XIN)	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 4.0 to 5.5 V Double-speed mode			4	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 2.4 to 5.5 V Double-speed mode			2	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 4.0 to 5.5 V High-, Middle-speed mode			8	MHz
	Oscillation frequency (Note 3) at ceramic oscillation or external clock input	V _{CC} = 2.4 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	V _{CC} = 4.0 to 5.5 V High-, Middle-speed mode			4	MHz
	Oscillation frequency (Note 3) at RC oscillation	V _{CC} = 2.4 to 5.5 V High-, Middle-speed mode			2	MHz

Notes 1: The peak output current is the peak current flowing in each port.

2: The average output current I_{OL} (avg), I_{OH} (avg) in an average value measured over 100 ms.

3: When the oscillation frequency has a duty cycle of 50 %.

Table 29 Electrical characteristics

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
VOH	“H” output voltage P00–P07, P10–P14, P20–P25, P30–P34, P37 (Note 1)	I _{OH} = –5 mA V _{CC} = 4.0 to 5.5 V	V _{CC} –1.5			V
		I _{OH} = –1.0 mA V _{CC} = 2.4 to 5.5 V	V _{CC} –1.0			V
VOL	“L” output voltage P00–P07, P10–P14, P20–P25, P37	I _{OL} = 5 mA V _{CC} = 4.0 to 5.5 V			1.5	V
		I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
		I _{OL} = 1.0 mA V _{CC} = 2.4 to 5.5 V			1.0	V
VOL	“L” output voltage P30–P34	I _{OL} = 15 mA V _{CC} = 4.0 to 5.5 V			2.0	V
		I _{OL} = 1.5 mA V _{CC} = 4.0 to 5.5 V			0.3	V
		I _{OL} = 10 mA V _{CC} = 2.4 to 5.5 V			1.0	V
VT+–VT–	Hysteresis CNTR0, INT0, (Note 2) P00–P07 (Note 3)			0.4		V
VT+–VT–	Hysteresis RXD, SCLK, SDATA (Note 2)			0.5		V
VT+–VT–	Hysteresis RESET			0.5		V
I _{IH}	“H” input current P00–P07, P10–P14, P20–P25, P30–P34, P37	V _I = V _{CC} (Pin floating. Pull up transistors “off”)			5.0	μA
I _{IH}	“H” input current RESET	V _I = V _{CC}			5.0	μA
I _{IH}	“H” input current X _{IN}	V _I = V _{CC}		4.0		μA
I _{IL}	“L” input current P00–P07, P10–P14, P20–P25, P30–P34, P37	V _I = V _{SS} (Pin floating. Pull up transistors “off”)			–5.0	μA
I _{IL}	“L” input current RESET, CNV _{SS}	V _I = V _{SS}			–5.0	μA
I _{IL}	“L” input current X _{IN}	V _I = V _{SS}		–4.0		μA
I _{IL}	“L” input current P00–P07, P30–P34, P37	V _I = V _{SS} (Pull up transistors “on”)		–0.2	–0.5	mA
V _{RAM}	RAM hold voltage	When clock stopped	2.0		5.5	V
I _{CC}	Power source current	High-speed mode, f(X _{IN}) = 8 MHz Output transistors “off”		5.0	8.0	mA
		High-speed mode, f(X _{IN}) = 2 MHz, V _{CC} = 2.4 V Output transistors “off”		0.5	1.5	mA
		Double-speed mode, f(X _{IN}) = 4 MHz Output transistors “off”		5.0	8.0	mA
		Middle-speed mode, f(X _{IN}) = 8 MHz, Output transistors “off”		2.0	5.0	mA
		f(X _{IN}) = 8 MHz (in WIT state) Functions except Timer 1 and Timer 2 stop Output transistors “off”		1.6	3.2	mA
		f(X _{IN}) = 2 MHz, V _{CC} = 2.4 V (in WIT state) Output transistors “off”		0.2		mA
		Increment when A-D conversion is executed f(X _{IN}) = 8 MHz, V _{CC} = 5 V		0.5		mA
		All oscillation stopped (in STP state) Output transistors “off”	T _a = 25 °C	0.1	1.0	μA
			T _a = 125 °C		50	μA

Notes 1: P11 is measured when the P11/TxD P-channel output disable bit of the UART control register (bit 4 of address 001B16) is “0”.

2: RXD, SCLK, SDATA, and INT0 have hysteresises only when bits 0 to 2 of the port P1P3 control register are set to “0” (CMOS level).

3: It is available only when operating key-on wake up.

Table 30 A-D Converter characteristics

(V_{CC} = 2.7 to 5.5 V, V_{SS} = 0 V, T_a = -40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
—	Resolution				10	Bits
—	Linearity error	V _{CC} = 2.7 to 5.5 V T _a = 25 °C			±3	LSB
—	Differential nonlinear error	V _{CC} = 2.7 to 5.5 V T _a = 25 °C			±0.9	LSB
VOT	Zero transition voltage	V _{CC} = V _{REF} = 5.12 V	0	5	20	mV
		V _{CC} = V _{REF} = 3.072 V	0	3	15	mV
VFST	Full scale transition voltage	V _{CC} = V _{REF} = 5.12 V	5105	5115	5125	mV
		V _{CC} = V _{REF} = 3.072 V	3060	3069	3075	mV
tCONV	Conversion time				122	t _c (X _{IN})
RLADDER	Ladder resistor			55		kΩ
I _{VREF}	Reference power source input current	V _{REF} = 5.0 V	50	150	200	μA
		V _{REF} = 3.0 V	30	70	120	
I _{I(AD)}	A-D port input current				5.0	μA

Table 31 Timing requirements (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _w (RESET)	Reset input "L" pulse width	15			μs
t _c (XIN)	External clock input cycle time	125			ns
t _{WH} (XIN)	External clock input "H" pulse width	50			ns
t _{WL} (XIN)	External clock input "L" pulse width	50			ns
t _c (CNTR)	CNTR ₀ input cycle time	200			ns
t _{WH} (CNTR)	CNTR ₀ , INT ₀ input "H" pulse width	80			ns
t _{WL} (CNTR)	CNTR ₀ , INT ₀ input "L" pulse width	80			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	1000			ns
t _{WH} (SCLK)	Serial I/O2 clock input "H" pulse width	400			ns
t _{WL} (SCLK)	Serial I/O2 clock input "L" pulse width	400			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time	200			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time	200			ns

Table 32 Timing requirements (2)

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _w (RESET)	Reset input "L" pulse width	35			μs
t _c (XIN)	External clock input cycle time	250			ns
t _{WH} (XIN)	External clock input "H" pulse width	100			ns
t _{WL} (XIN)	External clock input "L" pulse width	100			ns
t _c (CNTR)	CNTR ₀ input cycle time	500			ns
t _{WH} (CNTR)	CNTR ₀ , INT ₀ , input "H" pulse width	230			ns
t _{WL} (CNTR)	CNTR ₀ , INT ₀ , input "L" pulse width	230			ns
t _c (SCLK)	Serial I/O2 clock input cycle time	2000			ns
t _{WH} (SCLK)	Serial I/O2 clock input "H" pulse width	950			ns
t _{WL} (SCLK)	Serial I/O2 clock input "L" pulse width	950			ns
t _{su} (SCLK–SDATA)	Serial I/O2 input set up time	400			ns
t _h (SCLK–SDATA)	Serial I/O2 input hold time	400			ns

Table 33 Switching characteristics (1)

(V_{CC} = 4.0 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 125 °C, unless otherwise noted)

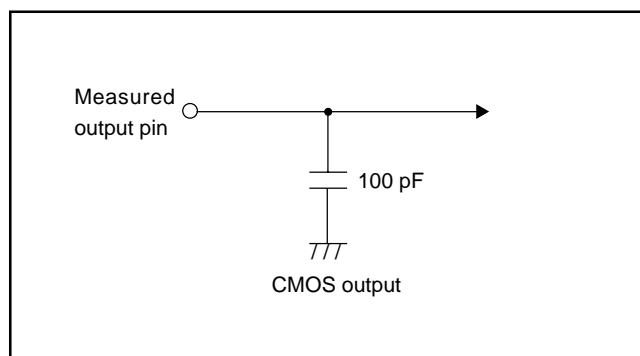
Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _C (SCLK)/2–50			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _C (SCLK)/2–50			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			200	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			50	ns
t _f (SCLK)	Serial I/O2 clock output falling time			50	ns
t _r (CMOS)	CMOS output rising time (Note 1)		10	50	ns
t _f (CMOS)	CMOS output falling time (Note 1)		10	50	ns

Note 1: Pin XOUT is excluded.

Table 34 Switching characteristics (2)

(V_{CC} = 2.4 to 5.5 V, V_{SS} = 0 V, T_a = –40 to 125 °C, unless otherwise noted)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
t _{WH} (SCLK)	Serial I/O2 clock output “H” pulse width	t _C (SCLK)/2–80			ns
t _{WL} (SCLK)	Serial I/O2 clock output “L” pulse width	t _C (SCLK)/2–80			ns
t _d (SCLK–SDATA)	Serial I/O2 output delay time			400	ns
t _v (SCLK–SDATA)	Serial I/O2 output valid time	0			ns
t _r (SCLK)	Serial I/O2 clock output rising time			80	ns
t _f (SCLK)	Serial I/O2 clock output falling time			80	ns
t _r (CMOS)	CMOS output rising time (Note 1)		20	80	ns
t _f (CMOS)	CMOS output falling time (Note 1)		20	80	ns

Note 1: Pin XOUT is excluded.

Fig. 49 Switching characteristics measurement circuit diagram
(Extended operating temperature 125 °C version)

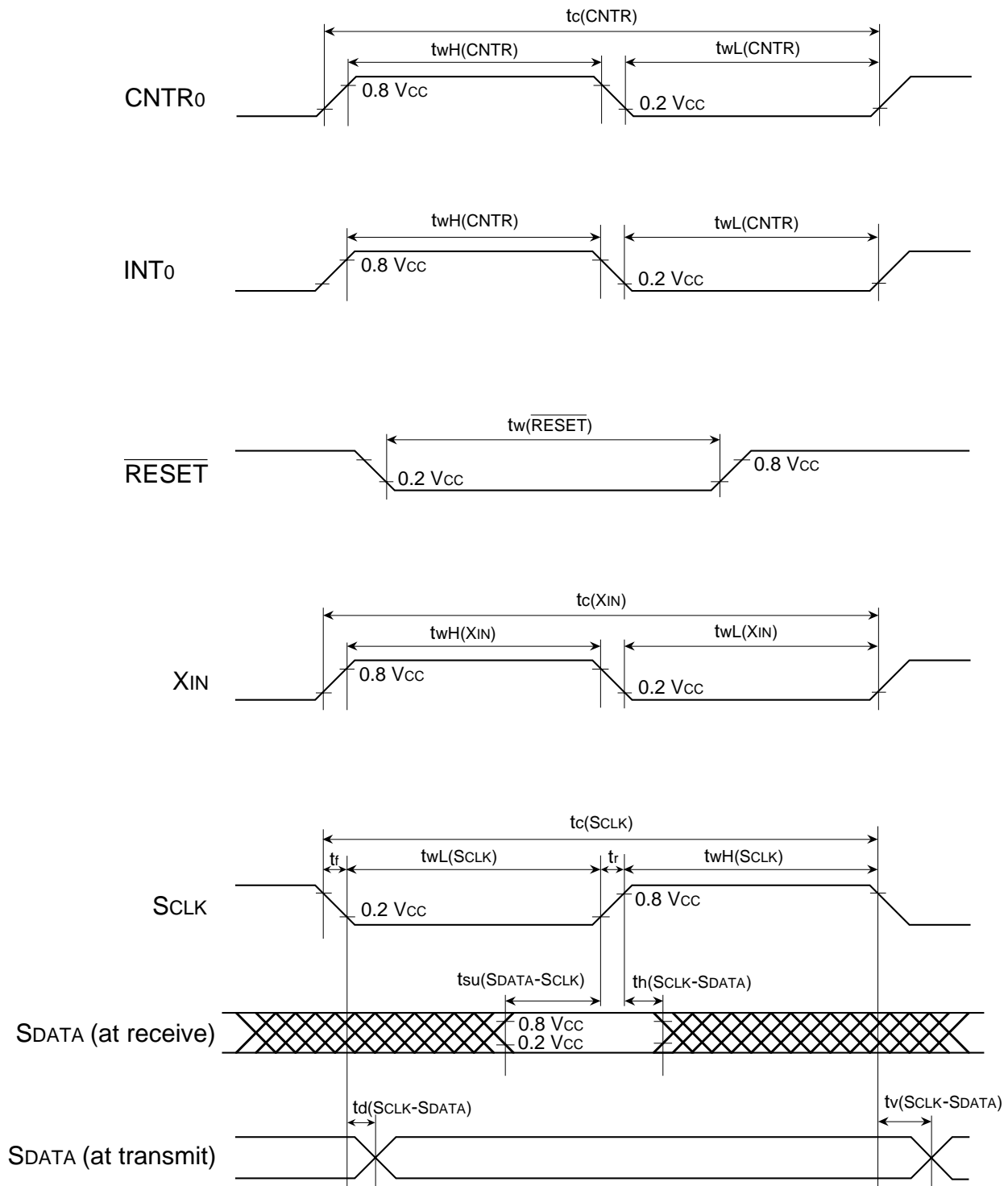
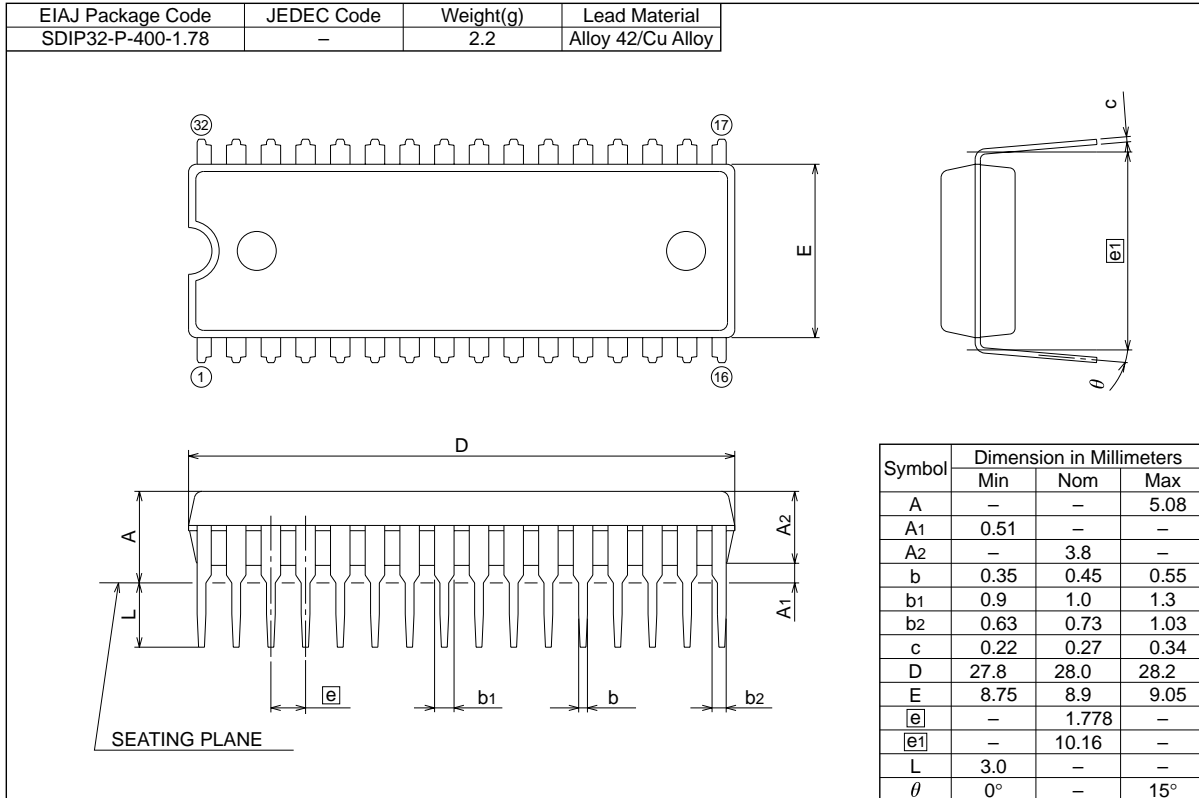


Fig. 50 Timing chart (Extended operating temperature 125 °C version)

PACKAGE OUTLINE

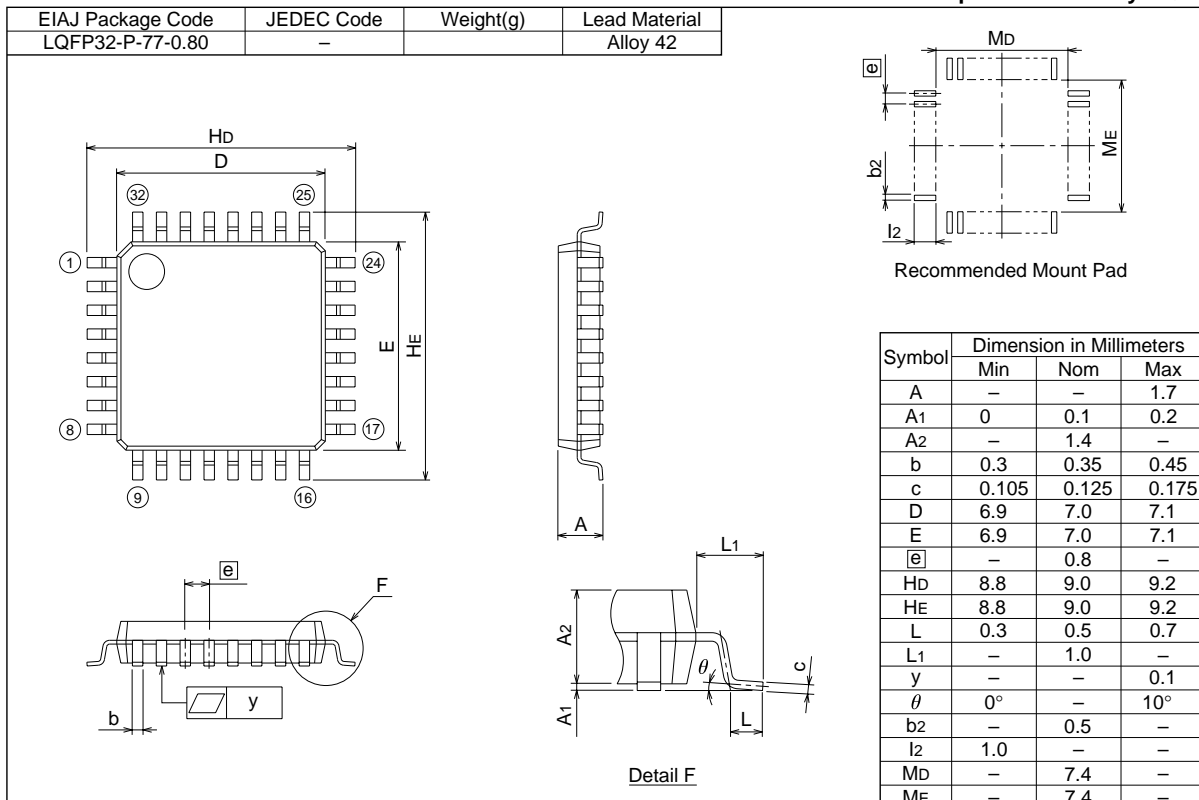
32P4B

Plastic 32pin 400mil SDIP



32P6B-A

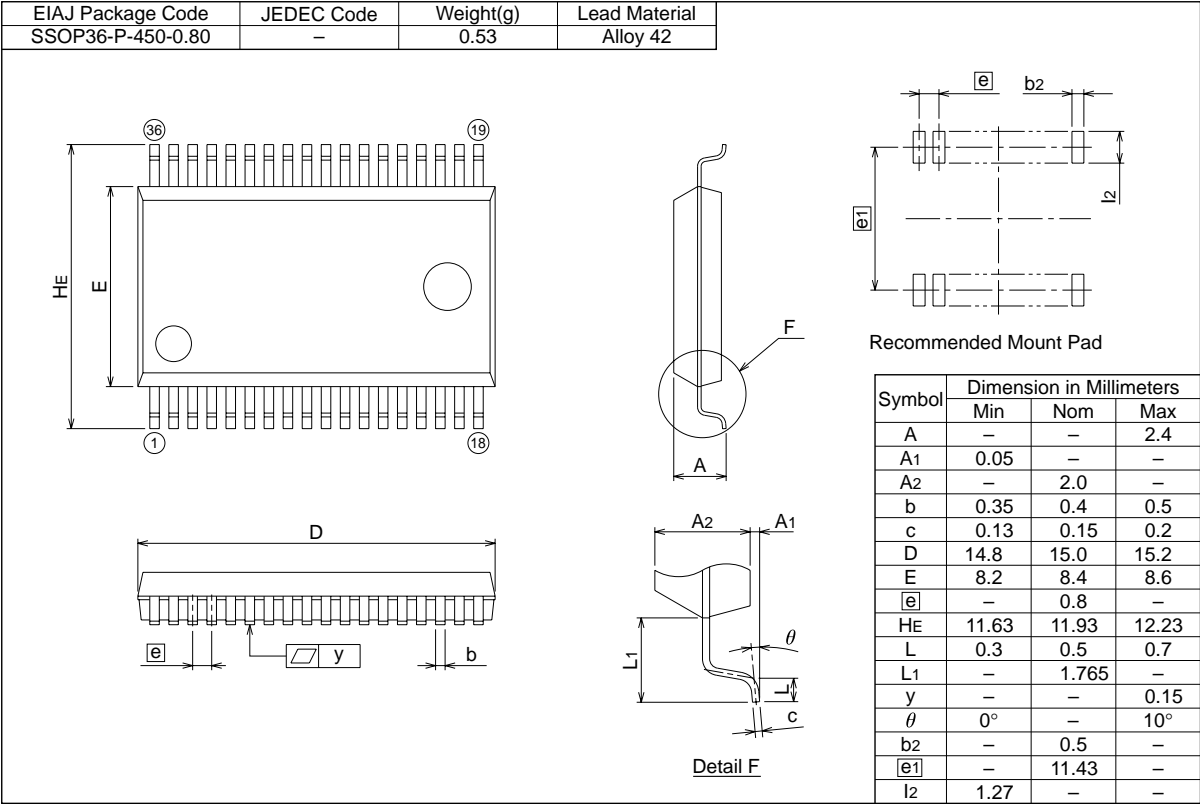
Plastic 32pin 7X7mm body LQFP



36P2R-A

EIAJ Package Code	JEDEC Code	Weight(g)	Lead Material
SSOP36-P-450-0.80	—	0.53	Alloy 42

Plastic 36pin 450mil SSOP



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REVISION DESCRIPTION LIST

7531 Group DATA SHEET

Rev. No.	Revision Description	Rev. date
1.0	First Edition	970822
2.0	<p>Page 1; FEATURES</p> <p>In Programmable I/O ports, the pin number of 32-pin version is added.</p> <p>In Power source voltage, two conditions are added and two are revised.</p> <p>Page 8; Central Processing Unit (CPU)</p> <p>The name of manual, 740 Family Software Manual, is revised.</p> <p>Fig. 11; Note is added.</p> <p>Page 11; [Direction registers] PiD</p> <p>The sentences are revised: Pins set to input are floating, and permit reading pin values.</p> <p>Fig. 12; Bit function and the initial value are added.</p> <p>Fig. 13; The figure name is revised: port P1P3 control register.</p> <p>Page 15; Interrupt operation</p> <p>The order of No. 3 and 4 is revised.</p> <p>Fig. 17; Four bit names are revised: Serial I/O1.</p> <p>Page 21; [Serial I/O1 status register] SIO1STS</p> <p>Explanations are partly revised.</p> <p>Fig. 25; Bits 6 and 7 explanations of serial I/O1 control register are revised.</p> <p>Page 23; [Serial I/O2 control register] SIO2CON</p> <p>Explanations are partly revised.</p> <p>Fig. 26; Bit 3 explanations are revised. Note is partly revised.</p> <p>Page 27; Reset Circuit</p> <p>Explanations are partly revised: In the case of f(f)...</p> <p>Fig. 35; The waveform of clock from built-in ring oscillator is revised. Note 1 is revised.</p> <p>Fig. 36; (6) Port P1P3 control register is added.</p> <p>Page 32; A-D Converter</p> <p>Explanations are partly revised: The WIT instruction is eliminated.</p> <p>Page 33; DATA REQUIRED FOR ROM PROGRAMMING ORDERS</p> <p>This clause is added.</p> <p>Table 7; Characteristics of Vcc is revised.</p> <p>Table 8; Characteristics of f(XIN) is revised.</p> <p>Table 9; Characteristics of Icc is revised.</p> <p>Table 12; Characteristics of tc(XIN), tWH(XIN), tWL(XIN), tc(CNTR), tWH(CNTR), tWL(CNTR), tc(SCLK), tWH(SCLK) and tWL(SCLK) are revised.</p> <p>Pages 42 to 45; MASK ROM CONFIRMATION FORM</p> <p>These are added.</p> <p>Pages 46 and 47; ROM PROGRAMMING CONFIRMATION FORM</p> <p>These are added.</p>	980220

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2.0	Pages 48 to 51; MARK SPECIFICATION FORM These are added. Pages 52 and 53; PACKAGE OUTLINE These are added.	980220
2.1	Pages 37, 46, 47; Some words are corrected. Pages 42 to 47; The numbers of Mask ROM and ROM Programming Confirmation Forms are revised. Page 49; 32P6B Mark Specification Form is revised.	980702
3.0	All pages; "PRELIMINARY Notice: This is ..." eliminated. All register structures; Initial values are added. Page 1; Explanations are partly revised. Page 1 and 2; Product names are added into the pin configurations. Page 3; Pin configuration of 42S1M is added. Page 8; Explanations of Figure 8 and Table 2 are partly revised. Page 9; Explanations of Figures 9 and 10 are partly revised. Page 11; The register name (Timer count source set register) is revised. Page 16; Table 4; The contents of "Remarks" is partly revised. Page 20; Explanation is revised. Page 21; The some word is added. Page 24; The some word is added. Explanation is revised. Page 26; Explanation is added. Page 27; Figure 34; Explanation is revised. Page 28; Period is added. Page 32; Figure titles of Figures 42 and 43 are revised. Page 33; Explanation is revised. Page 36 to 59; "ELECTRICAL CHARACTERISTICS" are all revised. "ELECTRICAL CHARACTERISTICS" of Extended operating temperature version is added. "ELECTRICAL CHARACTERISTICS" of Extended operating temperature 125 °C version is added. Page 60 to 71; "MASK ROM CONFIRMATION FORM" and "ROM PROGRAMMING CONFIRMATION FORM" are all revised. "SHRINK DIP MARK SPECIFICATION FORM" eliminated.	990212
4.0	Most of the contents (Functional Description, Electrical characteristics, and so on) are updated.	991115

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4.1	<p>Page 1: Power dissipation to 25 mW Operating temperature range; Note deleted</p> <p>Page 8: Fig. 8 “Under development” revised</p> <p>Page 10: Fig.11 Start address of Interrupt vector area to FFEC₁₆</p> <p>Page 25: Fig.29 Note revised</p> <p>Page 28: Description revised; $\overline{\text{RESET}}$ “L” pulse width 2 μs \rightarrow 15 μs</p> <p>Page 32: Fig.42 R_d resistor connected to XOUT pin eliminated</p> <p>Page 39: Table 12 Absolute accuracy (excluding quantization error) \rightarrow Linearity error</p> <p>Page 40: Table 13 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 15 μs Table 14 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 45 μs at V_{CC} = 2.2 to 5.5 V, 35 μs at V_{CC} = 2.4 to 5.5 V</p> <p>Page 47: Table 21 Absolute accuracy (excluding quantization error) \rightarrow Linearity error</p> <p>Page 48: Table 22 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 15 μs Table 23 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 35 μs</p> <p>Page 55: Table 30 Absolute accuracy (excluding quantization error) \rightarrow Linearity error</p> <p>Page 56: Table 31 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 15 μs Table 32 $t_w(\overline{\text{RESET}})$ revised; 2 μs \rightarrow 35 μs</p>	000615
4.2	Pages 28, 32: Character fonts errors revised	000905